

ODE Board

Off Detector Electronics for the muon system

INFN - LNF

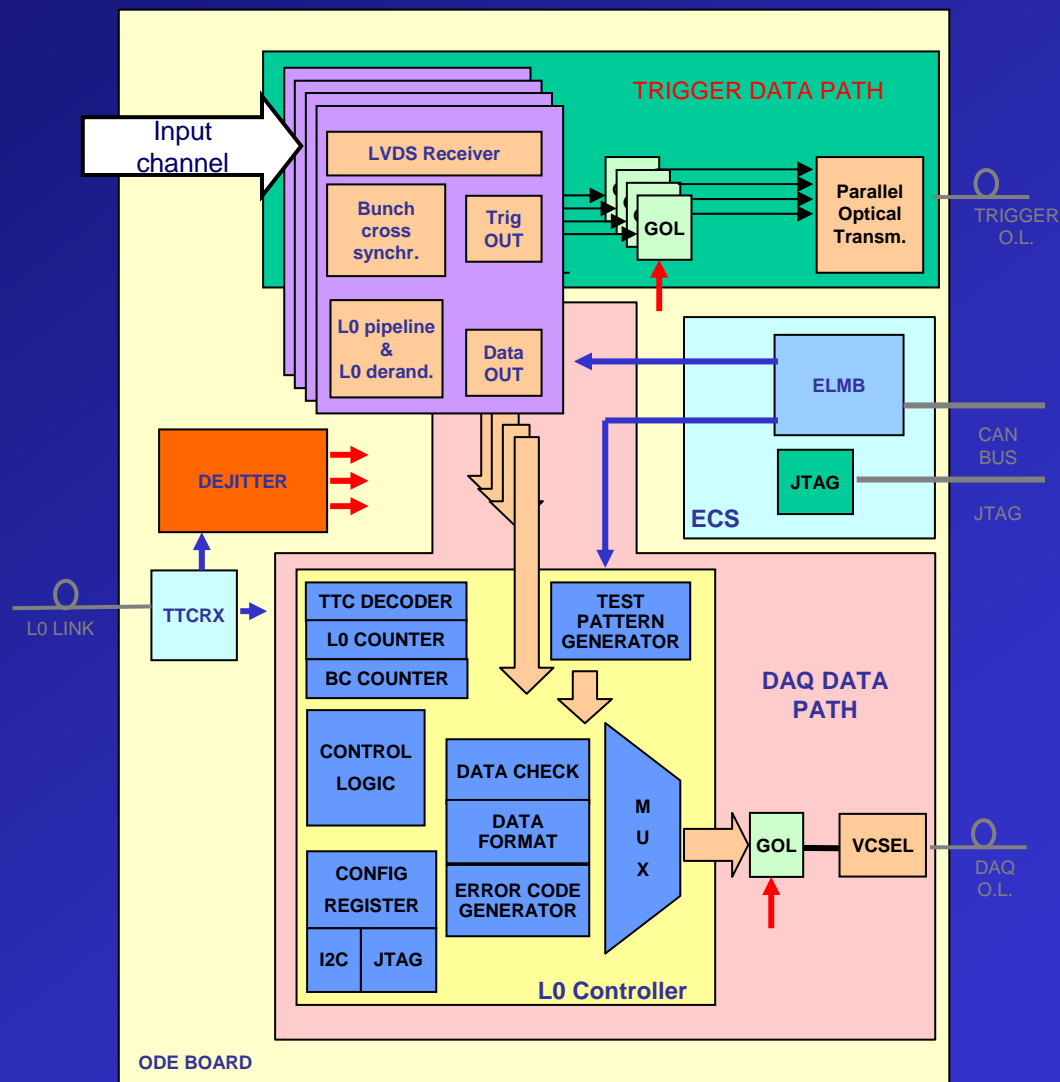
Servizio Elettronica Laboratori Frascati

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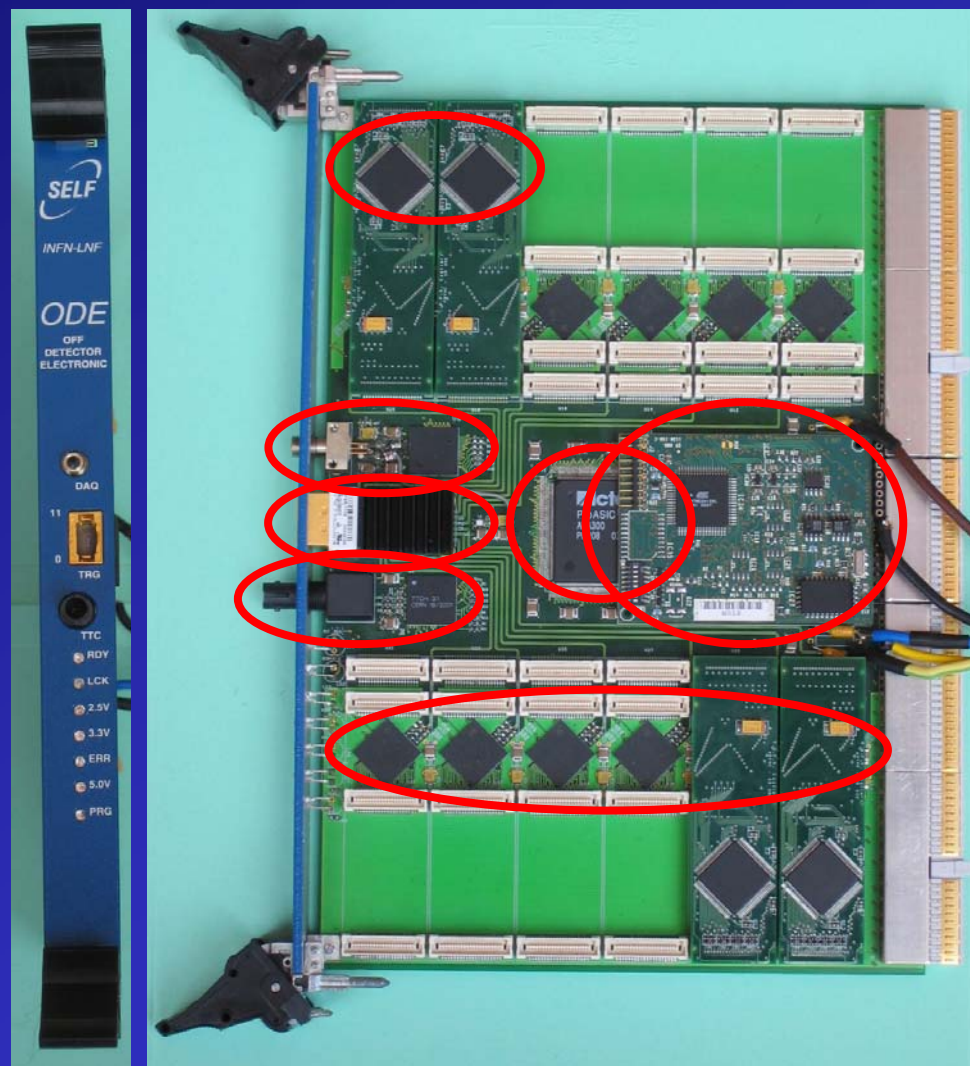
- ODE overview
 - Functionalities
 - Specs
- TTC system interface
 - Command and clock distribution
 - Measurements
- Trigger interface
 - Data flow and architecture
 - Performances
- DAQ Interface
 - Data flow and architecture
 - Performances
- ECS Interface
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- Radiation hardness assurance
- System tests
- Conclusions

ODE overview

- L0 front-end electronics stage
 - Clock synchronization
 - Bx alignment
 - L0 pipelining and buffering
- TTC system interface
 - Master LHCb clock
 - L0 trigger and reset signals
- Clock de-jitter and distribution
- L0 trigger interface
 - Trigger Unit production
 - Parallel optical link
- L1 DAQ interface
 - Data formatting
 - Single optical link
- FPGA L0 board controller
 - TTC commands decoder
 - DAQ data formatting
 - Test facilities and diagnostic
- ECS interface
 - Initialization, monitor and debug
 - CANbus link

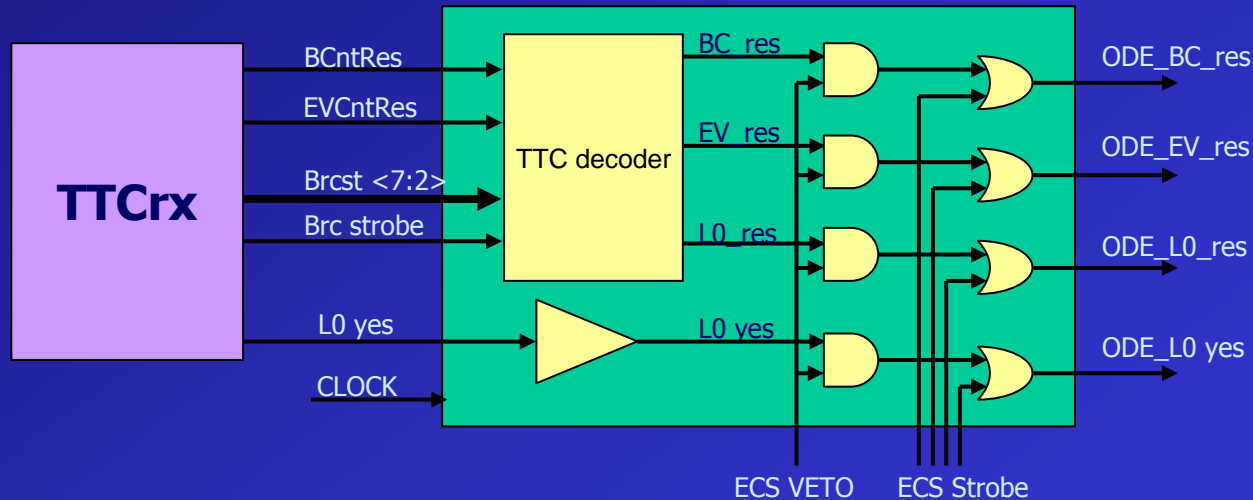


- L0 front-end electronics stage
 - 192 LVDS input signals
 - 24 SYNC chips (mounted on piggy board)
- TTC system interface
 - 1 optical receiver + 1 TTCrx chip
- Clock de-jitter and distribution
 - 1 QPLL chip
 - Tree network based on MC100LVEP family
- L0 trigger interface (12 traces @ 1.6Gbit/s)
 - 12 GOL chips + 1 parallel optical transmitter
- L1 DAQ interface (1 trace @ 1.6Gbit/s)
 - 1 GOL chip + 1 VCSEL diode
- FPGA board controller
 - Flash RAM based Actel FPGA (ProAsicPlus)
 - 3 buses (32 bit) for SYNC and GOL interfaces
 - 154 I/O pin used (99%)
- ECS interface
 - 1 ELMB board
 - CANbus link on the backplane
 - 2 I²C internal buses
- 6U Compact PCI card
 - 10 layers motherboard with controlled impedance
 - Mixed 5/3.3/2.5 V devices

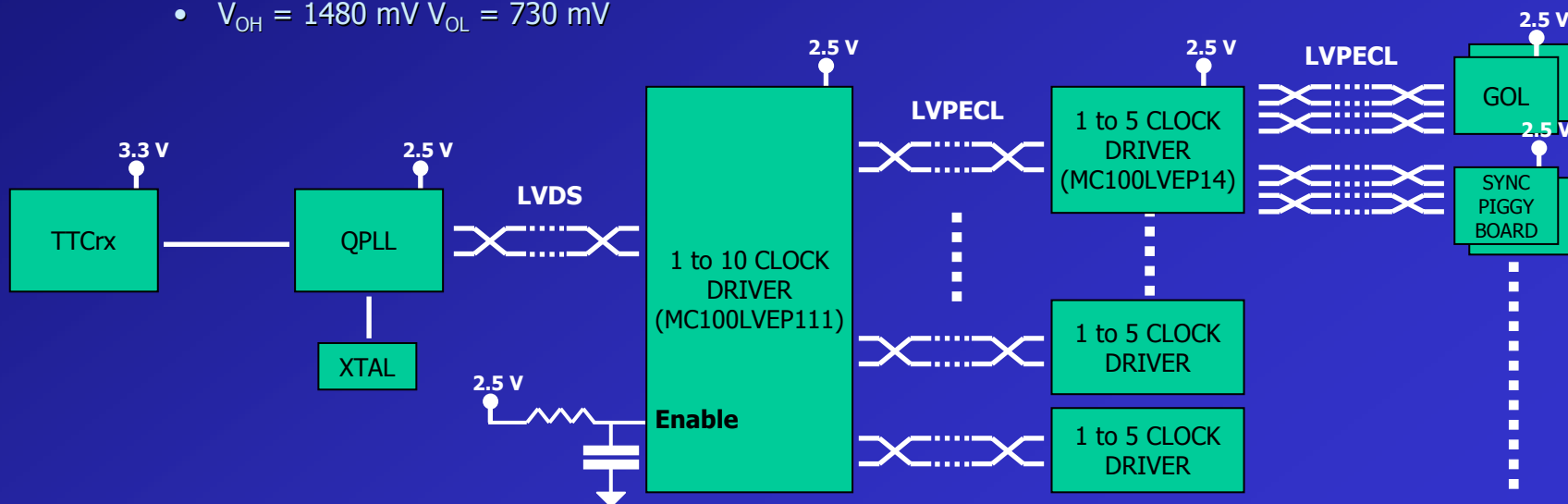


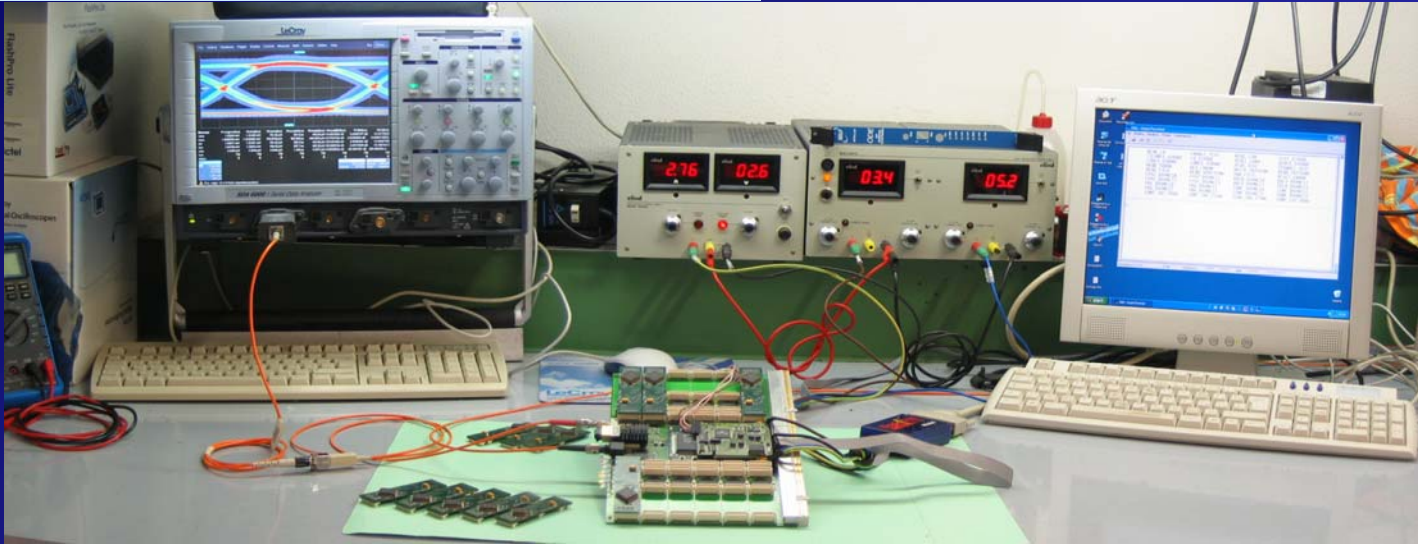
TTCrx and clock distribution

- TTC system interface is managed by the board controller
 - Receives signals from TTCrx
 - Decode broadcast command
 - Bunch-ID reset (BC_res) → Synchronous reset or preload for all ODE Bunch-ID counters
 - L0 Event ID reset (EV_res) → Synchronous reset for all ODE L0 Event-ID counters
 - L0 reset (L0_res) → Synchronous reset for all ODE L0 stages
 - Distributes L0 trigger and reset signals internally to the FPGA and to the SYNC chips
- The TTC reset signals do not modify the board configuration
 - No TTC resets delivered to GOL chips
 - ODE global reset (ODE default state) deliverable by ECS through ELMB



- LHCb clock (40.08 MHz) is received through the TTCrx chip
 - The ODE is a completely synchronous system
- TTCrx recovered clock must be de-jittered
 - TTCrx jitter > 240 ps peak-to-peak
 - Maximum allowed GOL jitter is 100 ps peak-to-peak
- QPLL chip is used to reduce the jitter (< 50 ps peak-to-peak)
- Low jitter clock distribution tree (**with enable**)
 - MC100LVEP family @ 2.5 V
 - Jitter less than 1 ps RMS
 - 150 ps Typical Device-to-Device Skew (20 ps Typical Output-to-Output Skew)
 - LVPECL standard
 - $V_{OH} = 1480$ mV $V_{OL} = 730$ mV



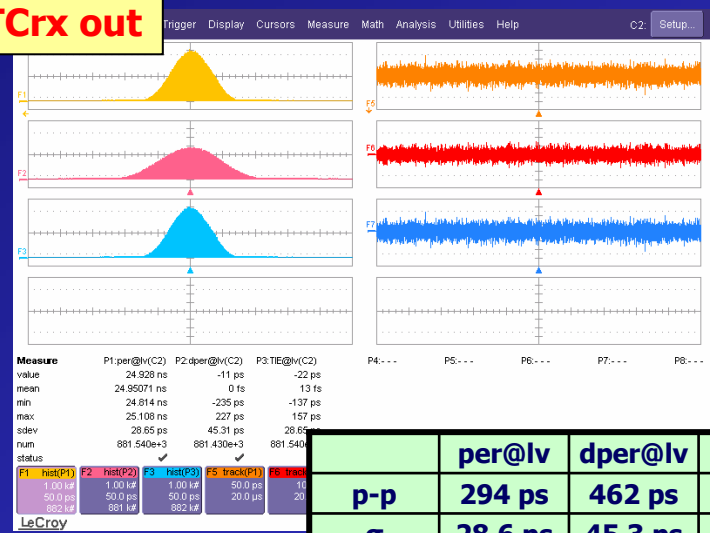


- LeCroy SDA6000 with active differential probe (LeCroy mod. D600AT)
 - 6 GHz Bandwidth
 - 20 Gsample/s on two channels
 - 1 ps rms trigger jitter
 - Analysis on continuous acquired data stream
 - Analysis on consecutive interval unit or cycle
 - Trigger jitter free
- Jitter measurements
 - Per@level
 - Period at a specified level for every cycle in the waveform
 - Dper@level
 - Adjacent cycle deviation at a specified level (cycle-to-cycle jitter) of each cycle in the waveform
 - TIE@level
 - Difference between the measured times of crossing a given level and the ideal expected time

Jitter measurements

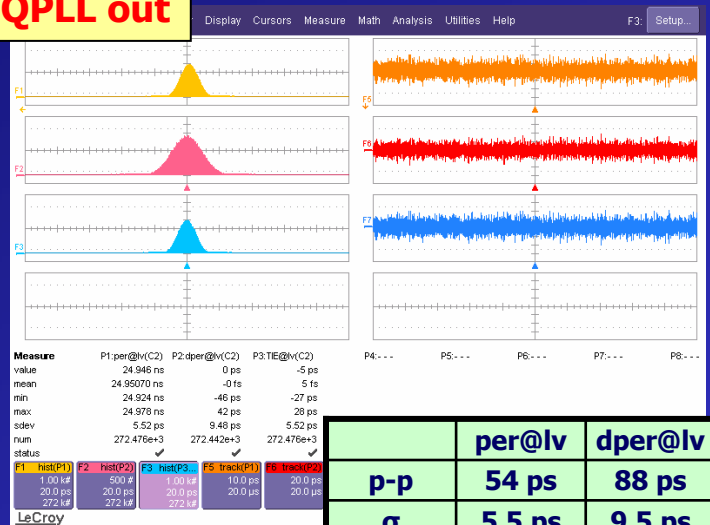
- Activity on both TTCrx channels via TTCvi + TTCvx boards:
 - ~ 20 MHz L0yes signal
 - ~ 400 KHz L0_res and EV_res signal
 - ~ 850 KHz BC_res signal
- Jitter at the GOL input well inside the specs
- Skew between clock lines < 300 ps

TTCrx out



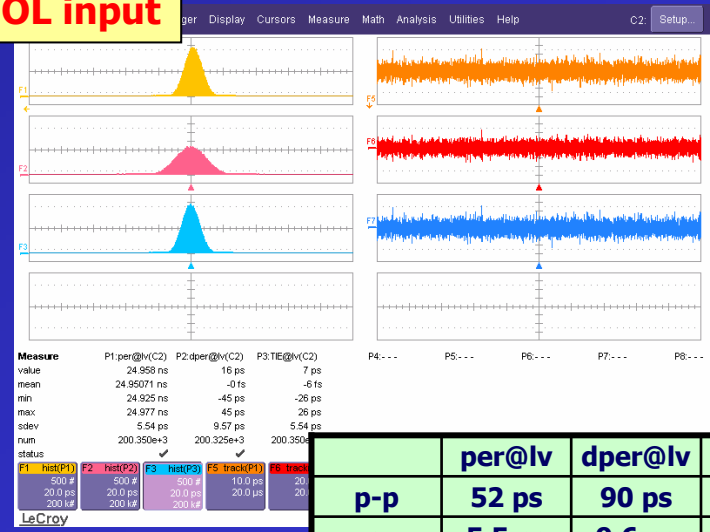
	per@lv	dper@lv	TIE@lv
p-p	294 ps	462 ps	294 ps
σ	28.6 ps	45.3 ps	28.6 ps

QPLL out



	per@lv	dper@lv	TIE@lv
p-p	54 ps	88 ps	55 ps
σ	5.5 ps	9.5 ps	5.5 ps

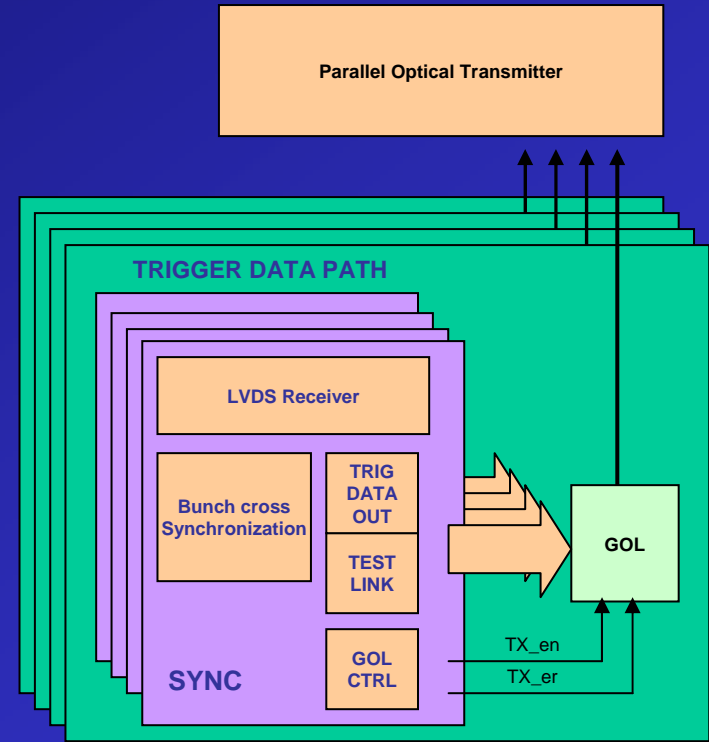
GOL input



	per@lv	dper@lv	TIE@lv
p-p	52 ps	90 ps	52 ps
σ	5.5 ps	9.6 ps	5.5 ps

L0 Trigger interface

- Unidirectional data transfer to trigger system
 - Logical channels merging to produce Trigger Unit (TU)
- Each SYNC chip for every machine cycle (40 MHz)
 - Receives and synchronizes 8 input signals
 - Assigns correct Bunch Crossing identifier (BX_Id)
 - Produces 10 bit data output (8 hits + 2 LSB of BX_Id)
- 2,3 or 4 SYNC chips per Trigger Unit
- 1 GOL chip per Trigger Unit
 - Transmission (tx_en, tx_er) driven by one "master" SYNC
 - Fast Ethernet mode (8B/10B)
- 12 GOL chips drive a parallel optical link
 - 12 links @ 1.6 Gbit/s each
 - Agilent HFBR772
- Test link facilities
 - Fixed or pseudo-random pattern
 - Check link integrity
 - BER test



- Trigger Unit configurations

Station	Region	Logical Channel per TU	SYNC per TU	Active channels per SYNC	TU per ODE (Active O.L.)	Active ODE Channels	# ODE
M1	R1	24	3	8	8	192	12
	R2						12
	R3						12
	R4						12
M2 or M3	R1	28	4	7	6	168	8 + 8
	R2	16	2	8	12	192	8 + 8
	R3	28	4	7	6	168	8 + 8
	R4	28	4	7	6	168	8 + 8
M4 or M5	R1	24	3	8	8	192	6 + 6
	R2	14	2	7	12	168	4 + 4
	R3	10	2	5	12	120	4 + 4
	R4	10	2	5	12	120	4 + 4

- Minimizing number of different PCB
 - Optimize performances
 - Improve maintenance
- Unique motherboard for all TU
 - 12 piggy board slots
 - 12 GOL chips
 - 6 / 8 / 12 active optical links
- 3 different piggy boards (PB)
 - 24 SYNC per ODE
 - 2 / 3+3 / 4 SYNC per piggy board (Type 3/2/1)
 - 120 / 168 / 192 active input signals

Trigger data format

- Trigger data format
 - SYNC data merged on piggy board to produce TU
 - Up to 28 data bits
 - 2 LSB of BX_Id
 - 2 switch bits to ensure data alignment in the trigger system

	31		15		0
1 st word	14 HIT DATA	0	1	14 HIT DATA	0 0
2 nd word	14 HIT DATA	0	1	14 HIT DATA	1 0
3 rd word	14 HIT DATA	1	1	14 HIT DATA	0 0
4 th word	14 HIT DATA	1	1	14 HIT DATA	1 0

BX_Id bit

Switch bit

- PB type 1: 4 SYNC – 7 bits per SYNC → 28 bits per TU



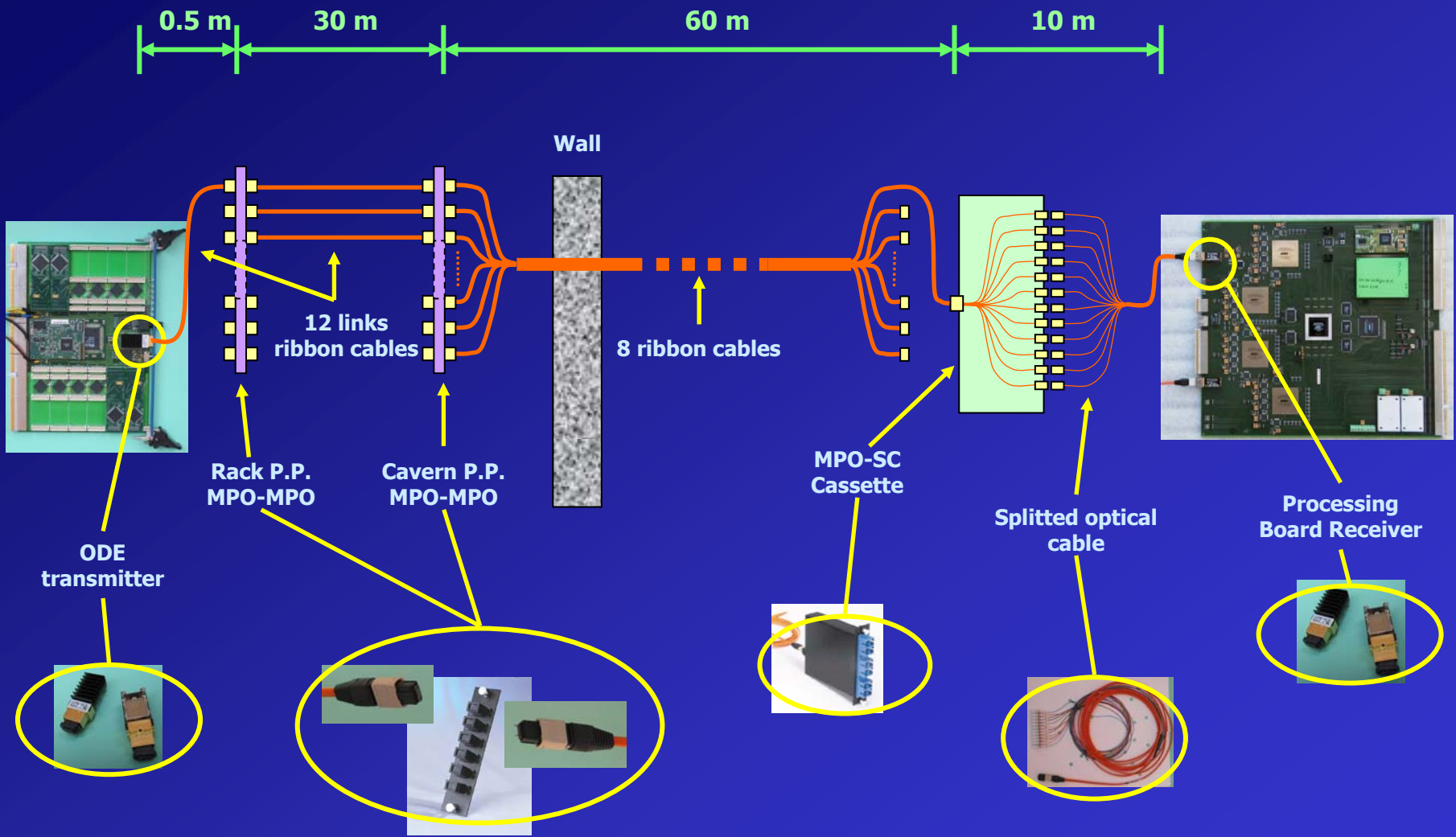
- PB type 2: 3+3 SYNC – 8 bits per SYNC → 24 bits per TU



- PB type 3: 2 SYNC – 8/7/5 bits per SYNC → 16/14/10 bits per TU



Trigger optical link

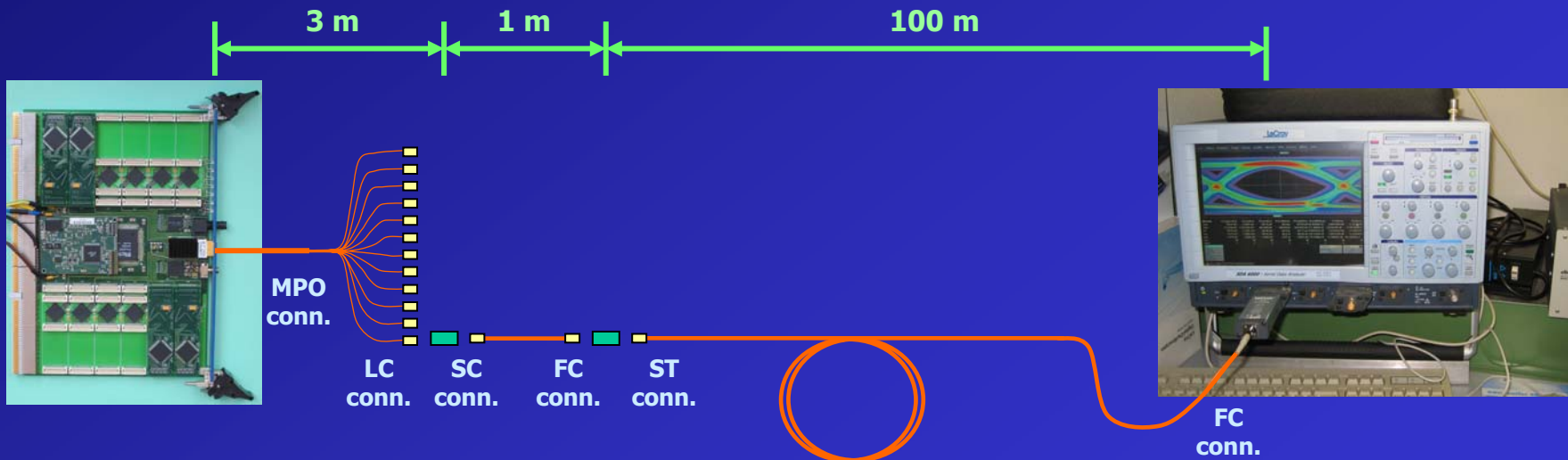


Trigger link performances

- Agilent HFBR772 transmitter
 - Output optical power
 - -8 dBm min (-4 dBm typ)
 - Extinction Ratio
 - 6 dB min. (7 dB typ)
 - Total jitter
 - 120 ps_{p-p} max (60 ps_{p-p} typ)
- ~ 100 m fiber
 - 850 nm, 50/125 μm, multimode
 - 3.5 dB/Km (TIA/EIA 568-B)
- 4 connections
 - 0.75 dB per connection (TIA/EIA 568-B)
- Agilent HFBR782 receiver
 - Input optical power sensitivity
 - -16 dBm max (-18.5 typ)
 - Input optical power saturation
 - -2 dBm min (-1 dBm typ)

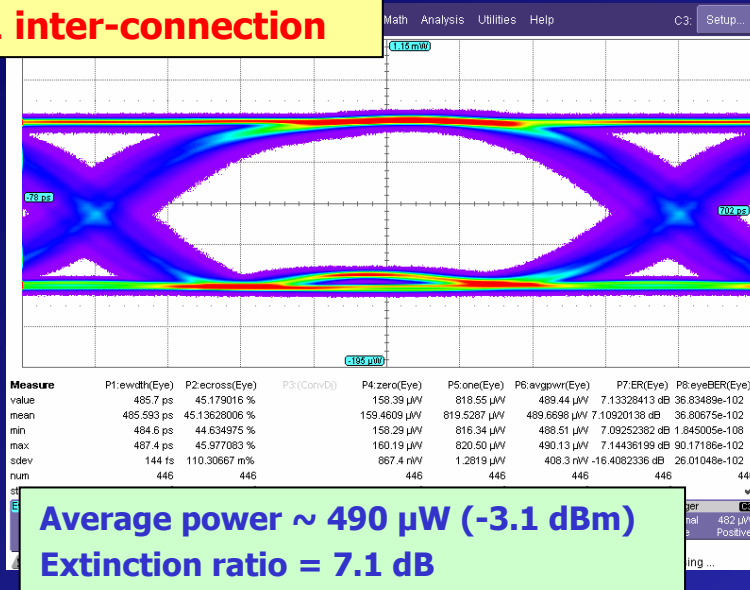
	Worst	Typ.	Unit
Output Optical Power	-8	-4	dBm avg.
Fiber attenuation	0.35	0.35	dB
Connectors attenuation	3	3	dB
Receiver input power	-11.35	-7.35	dBm avg.
Receiver sensitivity	-16	-18.5	dBm avg.
Power margin	4.65	11.15	dB

- Optical to electrical converter (LeCroy mod. OE425)
 - 4.5 GHz Bandwidth (500 – 870 nm)
 - Conversion factor 0.5 V/mW (@ 800 nm) → slightly deviation @ 850 nm
 - FC2125 standard reference receiver
 - FC Golden PLL (digital) for clock recovery
- Pseudo random bit sequence (2^8-1 bits)
 - 24 SYNC chips and 12 active GOL chips
 - 24 different seeds in PRBG
 - 16 input bits per GOL



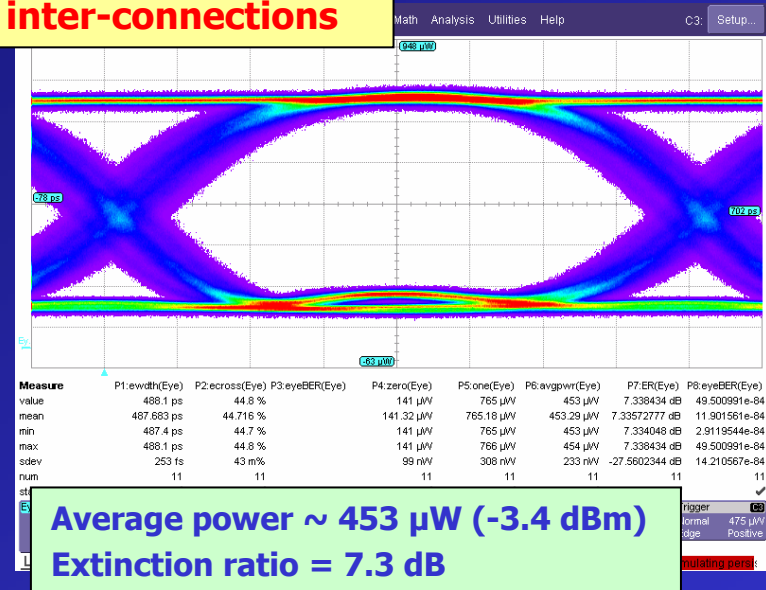
Eye Diagram

**4 m fiber
1 inter-connection**



**Average power $\sim 490 \mu\text{W}$ (-3.1 dBm)
Extinction ratio = 7.1 dB**

**~ 100 m fiber
2 inter-connections**

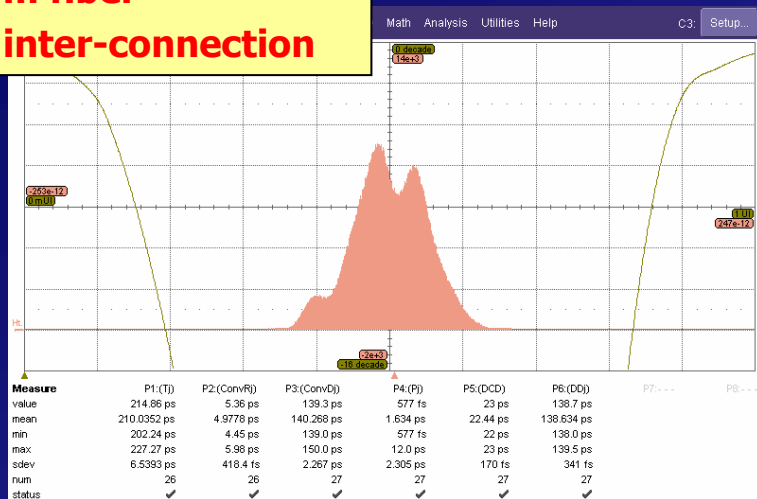


**Average power $\sim 453 \mu\text{W}$ (-3.4 dBm)
Extinction ratio = 7.3 dB**

- Good datasheet agreement with short fiber
 - Average power \rightarrow -4 dBm typ.
 - Extinction ratio \rightarrow 7 dB typ.
- Well open horizontal and vertical eye diagram after 100m
 - Good extinction ratio
 - Good power margin (12.6 dB)
 - Low attenuation (0.3 dB)

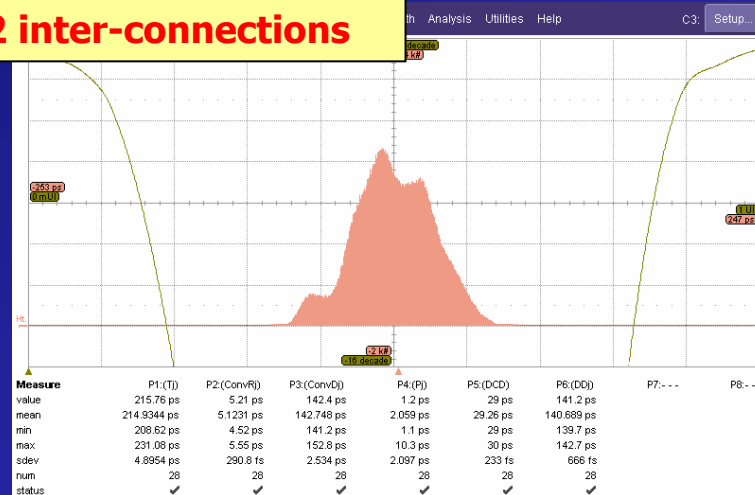
Bathtub curve

**4 m fiber
1 inter-connection**



BER $\sim 10^{-16}$ @ eye opening > 60%
Total jitter ~ 210 ps @ BER 10^{-12}

**~ 100 m fiber
2 inter-connections**



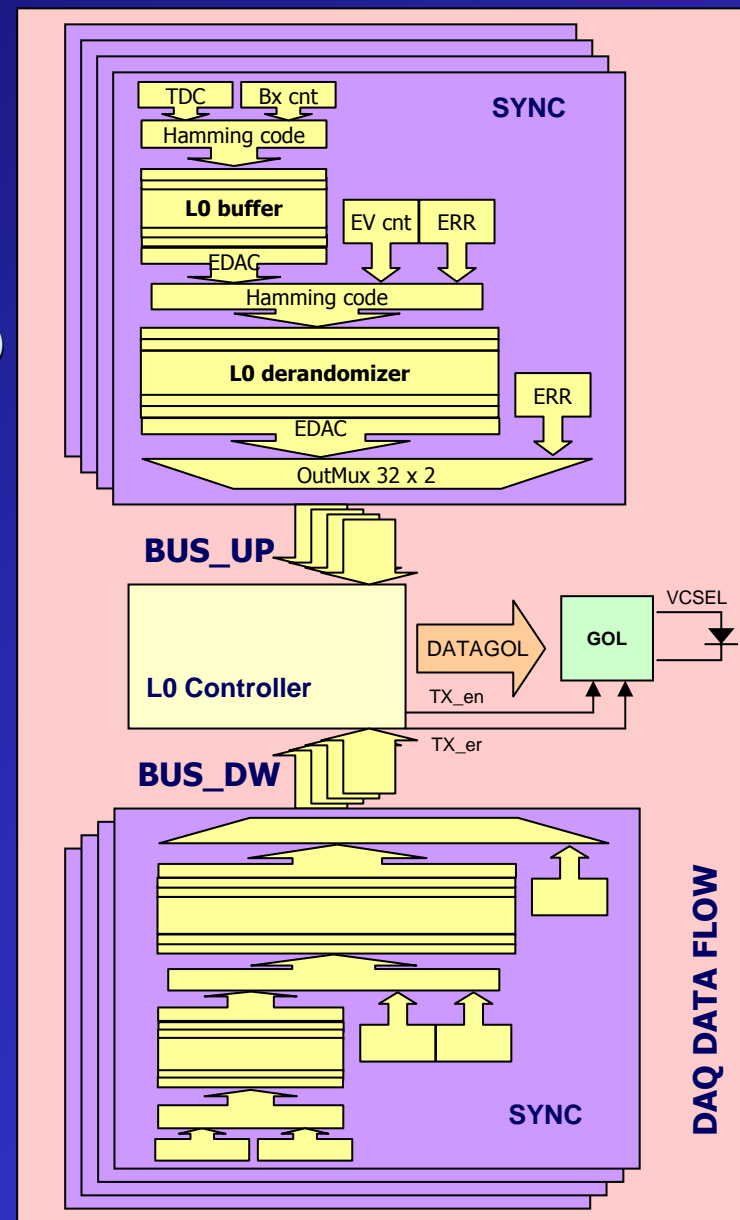
BER $\sim 10^{-16}$ @ eye opening > 60%
Total jitter ~ 215 ps @ BER 10^{-12}

- Analysis on Time Interval Error
 - Estimated BER only on time jitter
- Estimated BER lower than 10^{-16} compatible with a 60% eye open
 - Deserializer TLK2501 guarantees 10^{-12} with a 50% eye opening
- Total jitter $\sim 1/3$ of UI dominated by deterministic component
- Real bit error test up to 10^{-12} with 99% confidence level

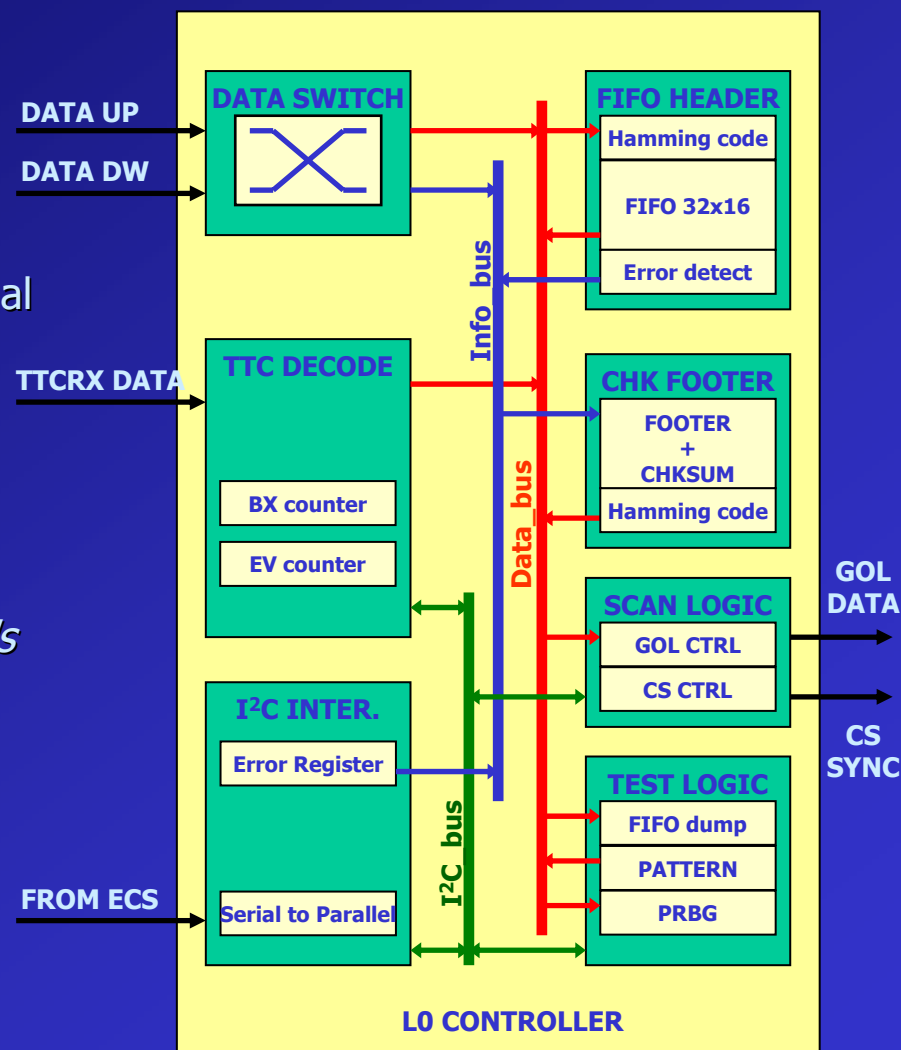
DAQ interface

DAQ data flow

- Unidirectional data transfer to L1 DAQ
- SYNC chips
 - Measure input signal phase in LHCb clock period
 - 4-bit TDC with 1.6 ns resolution
 - Put data in L0 buffer (40 MHz)
 - 4-bit TDC with 1.6 ns resolution
 - Put data in L0 derandomizer after L0 trigger (1 MHz)
- SYNC data format
 - 32 bits for TDC data (*dataword*)
 - 32 bits for BX_Id, EV_Id, data error (*infoword*)
 - 32 bits output data bus
 - 24 SYNC X 2 accesses X 25 ns = 1200 ns > 900 ns
- Parallel SYNC readout mode
 - 2 x 32 bits wide buses (BUS_UP, BUS_DW)
 - 12 SYNC for each bus
- L0 controller
 - Reads data/info words from SYNC derandomizers
 - Creates L1 DAQ data frame
 - Drives GOL (tx_en, tx_er)
 - Ethernet mode (8B/10B)
 - VCSEL diode

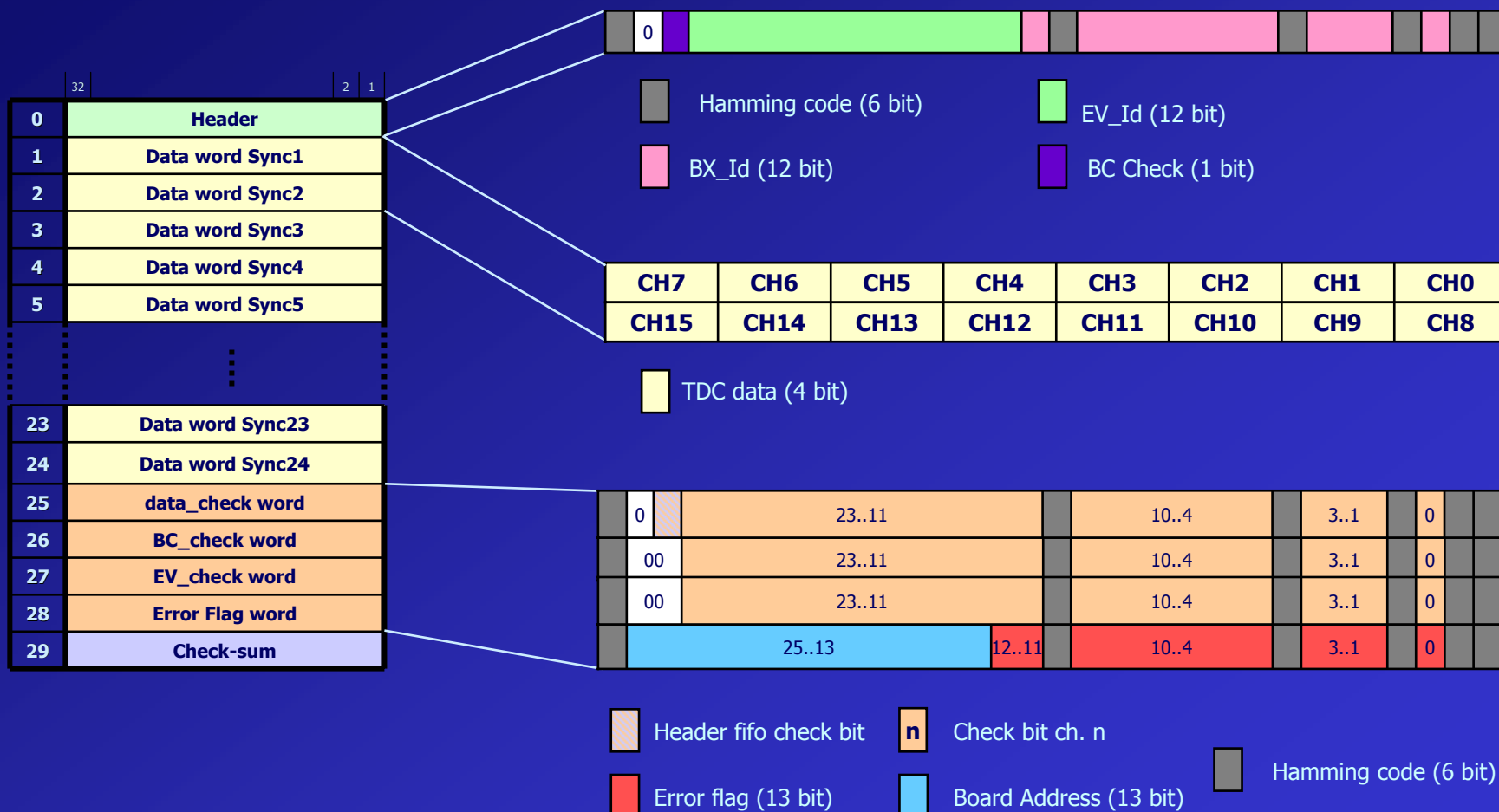


- Receives and decodes TTCrx data
- For each L0yes
 - Verifies TTCrx alignment
 - Generates a header word with internal BX_id and EV_id counters
 - Write the header in an internal FIFO
 - Up to 16 consecutive L0yes
- For each header word
 - Reads SYNC *datawords* and *infowords*
 - Verifies data alignment
 - Generates a footer words
 - Produces data frame for L1 DAQ
 - Drives GOL transmission
- Test facilities
- I²C interface

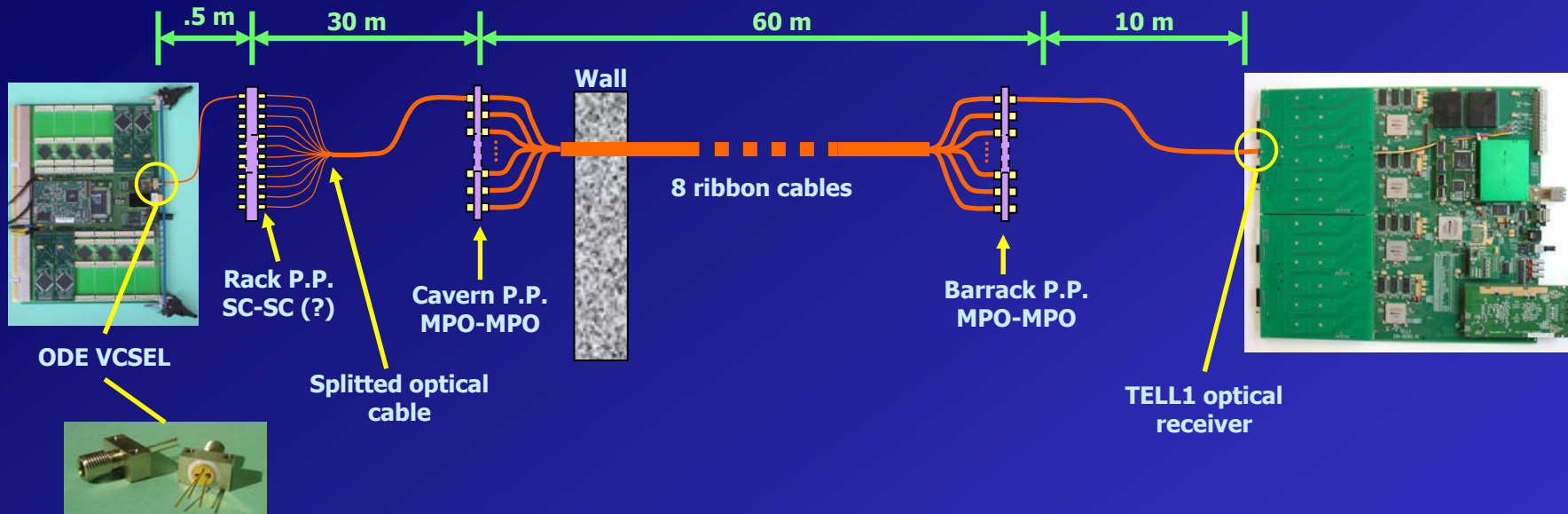


L1 data frame

- Data frame is preceded by an idle character
- Header and footer words hamming coded
- Data frame is 30 words long



- DAQ-SYNC Test Mode
 - Test DAQ data path
 - Known patterns loaded in SYNC L0 derandomizer via ECS
 - “Normal” data readout by board controller
- DAQ-Internal Test Mode
 - Test data link integrity and performances
 - Known patterns loaded in L0 board controller via ECS
 - 8 bits Pseudo-random sequence
- Trigger test mode
 - Test trigger link integrity and performances
 - Fixed pattern defined via ECS
 - 8 bits Pseudo-random sequence
- DAQ data dump
 - DAQ GOL frame dumped in a internal FIFO
 - DUMP mode programmable via ECS
- NO L0_YES needed in test mode
- All TTCrx signals emulated via ECS (L0_YES, BC_res, EV_res, L0_res)
- Error condition (TTCrx fault, DAQ GOL fault, SYNC error, etc.) stored in a STATUS register



- Photonics VCsel ULM850-05-TN-USMBOP

- 850 nm multimode VCsel
- Forward laser voltage $\rightarrow V_F = 2 \text{ V}$
- Threshold current $\rightarrow I_{th} = 1 \text{ mA}$
- Slope efficiency $\rightarrow \eta = 0.1 \text{ W/A}$
- Diff. series resistance $\rightarrow R_s = 60 \Omega$
- SMA package

- $\sim 100 \text{ m}$ fiber

- 850 nm, 50/125 μm , multimode
- 3.5dB/Km (TIA/EIA 568-B)

- 3 (4) connections

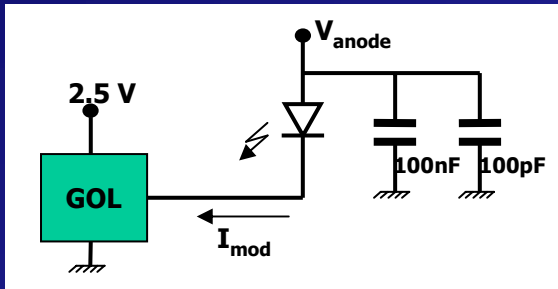
- 0.75 dB per connection (TIA/EIA 568-B)

- Receiver

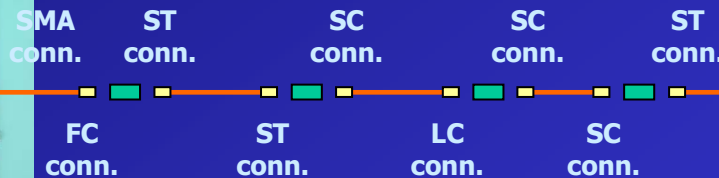
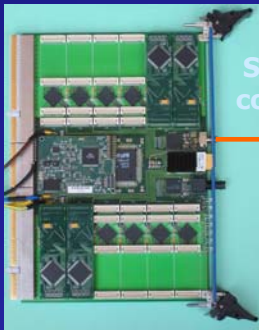
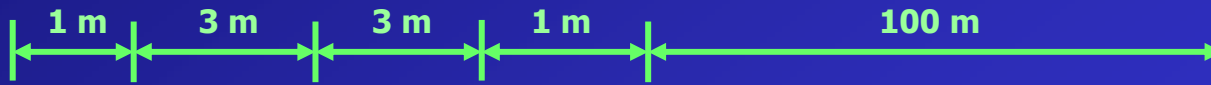
- Input optical power sensitivity
 - -16 dBm max (-18 typ)

Test setup

- GOL driver specs
 - Programmable bias current
 - Fixed modulation current = 10 mA
 - '1' level $\rightarrow I_{\text{mod}1} = I_{\text{bias}} + 10 \text{ mA}$
 - '0' level $\rightarrow I_{\text{mod}0} = I_{\text{bias}}$



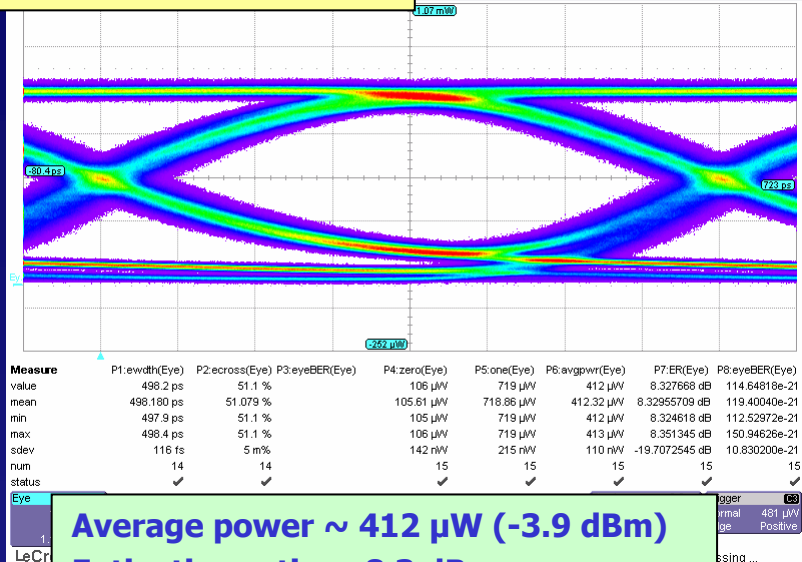
- $I_{\text{bias}} = 1.8 \text{ mA}$
 - Maximum continuous current 12 mA
 - Laser threshold current 1 mA
- VCsel anode voltage = 3.3 V
 - GOL driver voltage $> 1 \text{ V}$
- FC2125 standard reference receiver
- FC Golden PLL (digital) for clock recovery
- Pseudo random bit sequence ($2^{16}-1$ bits)



FC conn.

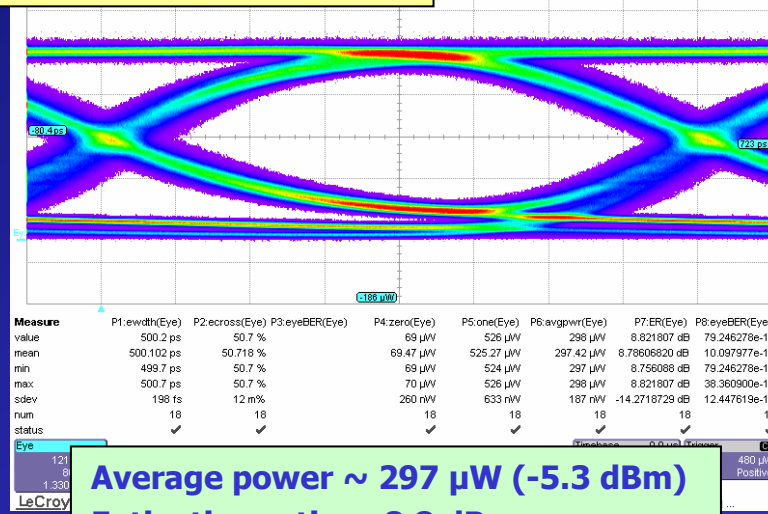
Eye diagram

1 m fiber



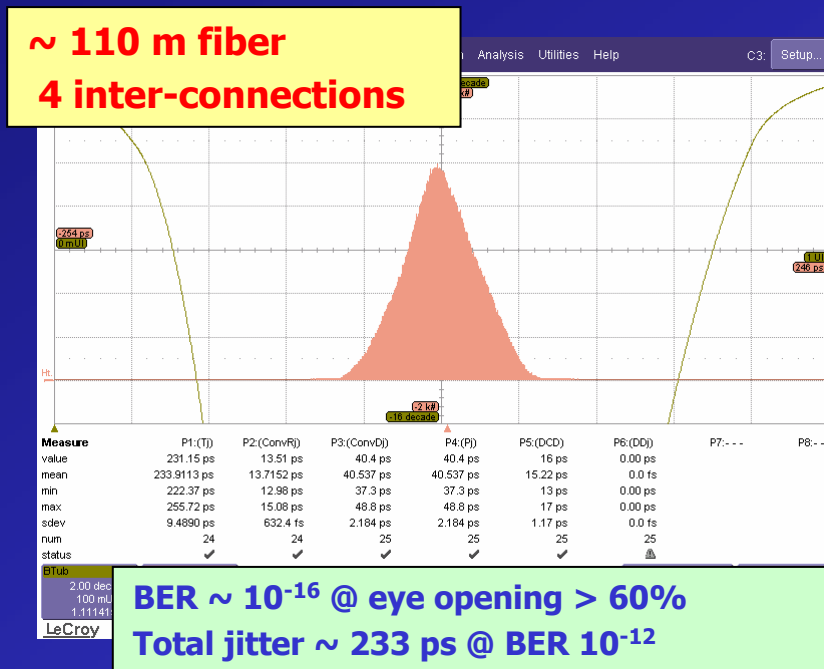
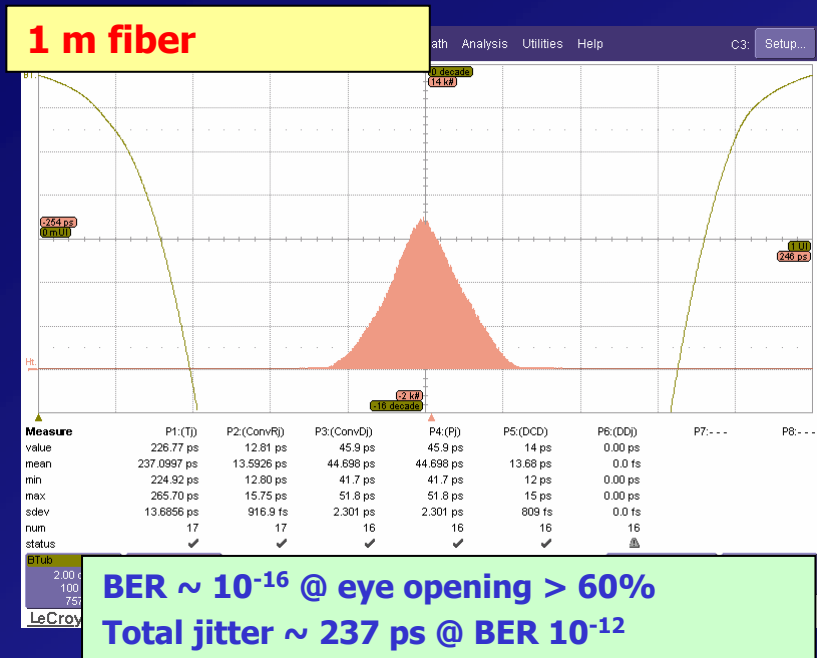
**Average power $\sim 412 \mu$ W (-3.9 dBm)
Extinction ratio = 8.3 dB**

**~ 110 m fiber
4 inter-connections**



**Average power $\sim 297 \mu$ W (-5.3 dBm)
Extinction ratio = 8.8 dB**

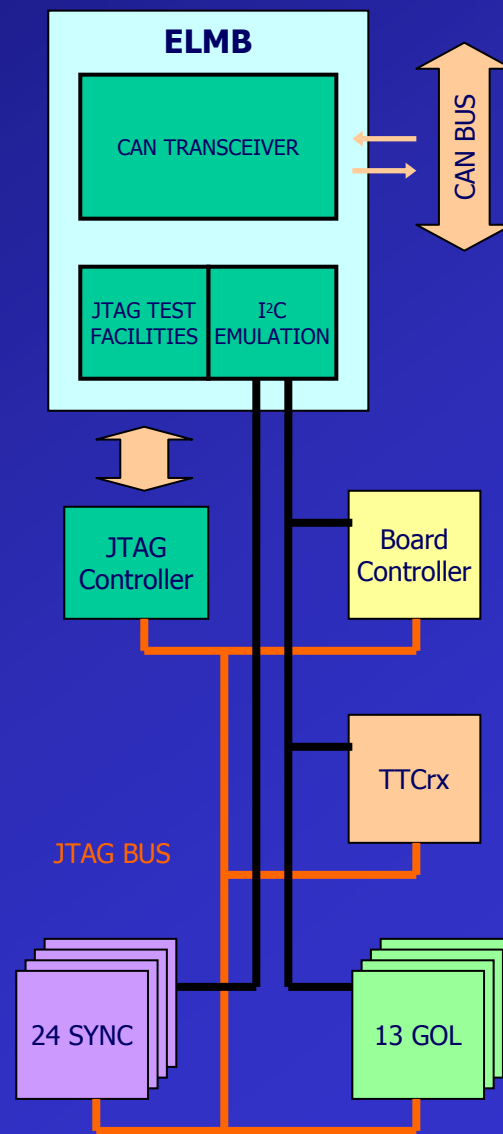
- Well open eye diagram
- Good extinction ratio
- Good power margin \rightarrow 10.7dB worst (12.7 dB typ)
- Attenuation \rightarrow 1.4 dB



- Estimated BER lower than 10^{-16} with 60% open eye
- Total jitter @ $10^{-12} \sim 1/3$ UI
- Real bit error test up to 10^{-12} with 99% confidence level

ECS interface

- ECS interface via ELMB card
 - ATmega128 μ processor with CAN controller
 - CANbus line on backplane
 - 1 branch with up to 16 ODE
 - 2 branches with up to 10 ODE each
- ELMB on-board connection
 - Global reset
 - Startup (programmable)
 - ECS (only way to reset TTCrx and GOL after startup)
 - 2 I²C bus
 - 24 SYNC
 - 13 GOL, TTCrx, L0 controller
 - Configuration, monitor, SYNC histogram read-out
 - 1 bus JTAG
 - Boundary scan
- CAN transceiver powered by ODE power supply
 - Optocoupler foreseen on the KVASER board (PCI-CAN interface) for galvanic isolation

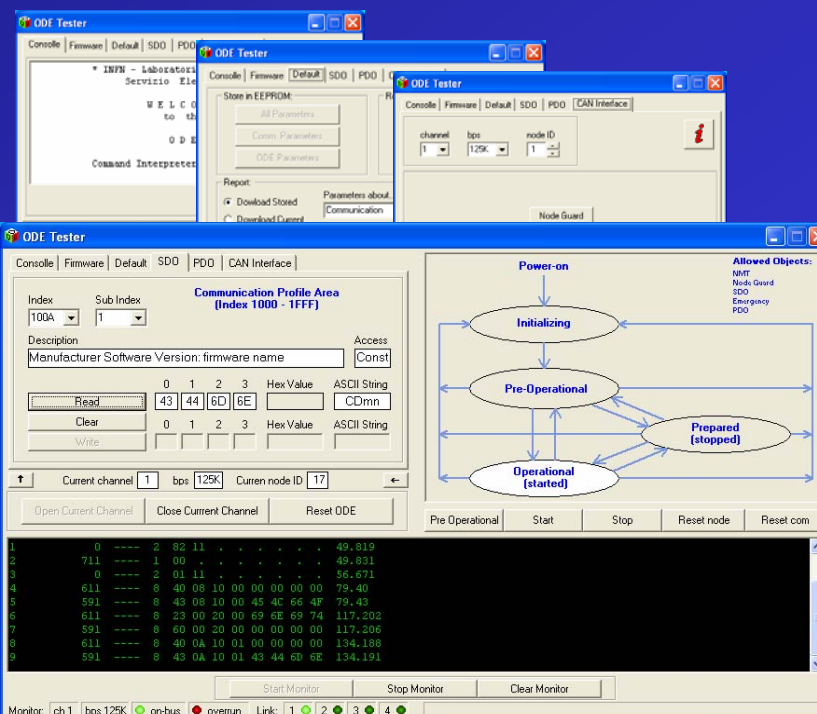
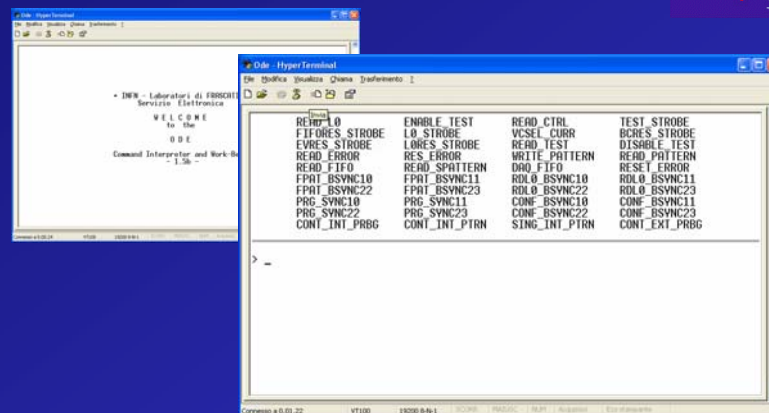


ELMB interface

- Serial interface for local access
 - RS232
 - Program on ELMB flash ram
 - Shell for command decoding

- CAN interface for remote access
 - CANopen standard protocol

- ODE tester program
 - Single *Object Dictionary* access via SDO or PDO
 - Node status monitor and control
 - Bus traffic monitor
 - Scripting language console for high level command
 - CAN-JTag command translator (to be implemented)
- PVSS console for ECS



GOL start-up problem

- “It was observed by several users that the GOL might fail to start-up correctly. When that happens, a chip reset is not able to restore normal operation.”
[GOL manual]
- A brief history
 - If CLOCK arrives before complete GOL power-up ...
 - Observed in the first ODE prototype
 - Enable on the clock network driven by 2.5 V
 - If the GOL is powered-up after other circuits that provide input signal to the GOL ...
 - **Never** observed on the ODE board
 - ALL chip powered at 2.5 V with the exception of TTCrx, ELMB and VCsel
 - When 2.5V is OFF and 3.3V is ON the 2.5V power plane goes at ~700 mV
 - TTCrx (through FPGA input pin) partially power the 2.5V plane
 - This voltage should be not enough to power partially the GOL chip
 - If the power-up is too slow...
 - **Never** observed on the ODE board
 - Test power-up sequence with ramp-up ranging from 5 ms to 250 ms
 - First 3.3 V ON and then 2.5 V ON

- The recommendations:
 - The power-up sequence must be validated for operating conditions identical to the ones to be used in the final systems ...
 - We do not have the final power supply (Wiener Maraton)
 - Anyhow power-up sequence can be defined in the final power supply
 - Use CRT4T ...
 - 13 GOL on the ODE motherboard
 - 13 chips
 - 13 control line
 - Also VCsel needed a CRT4T
 - **Huge change in the layout !!!**

It is really necessary?

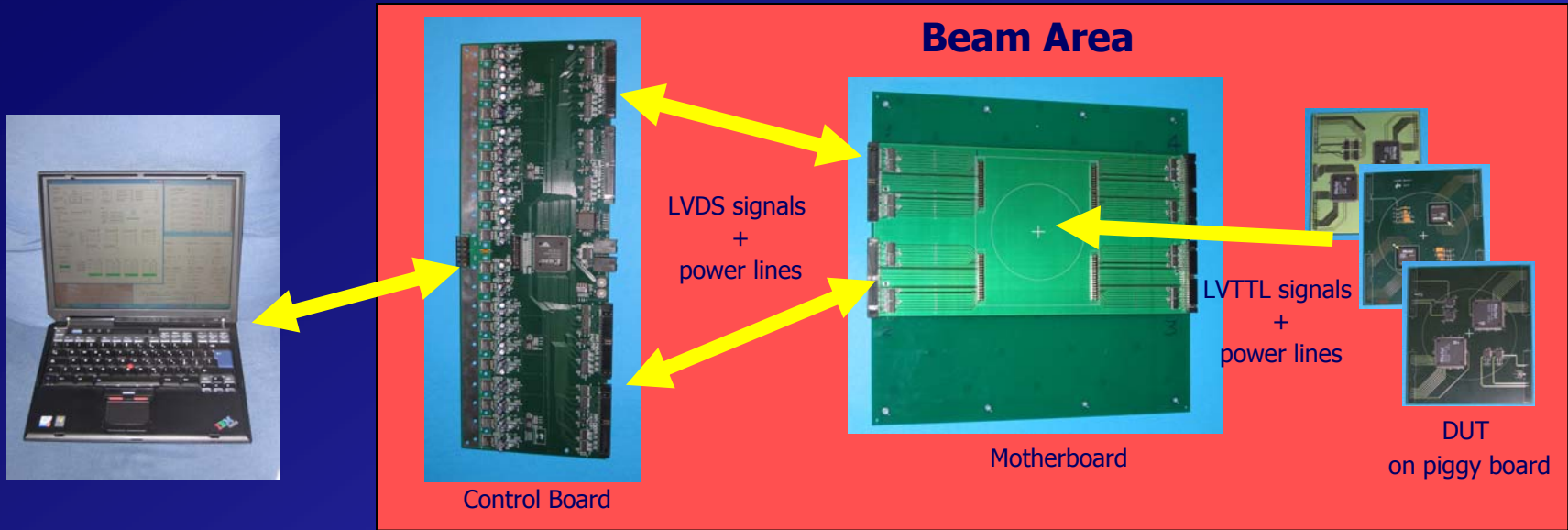
Radiation hardness assurance

Muon Radiation Environment

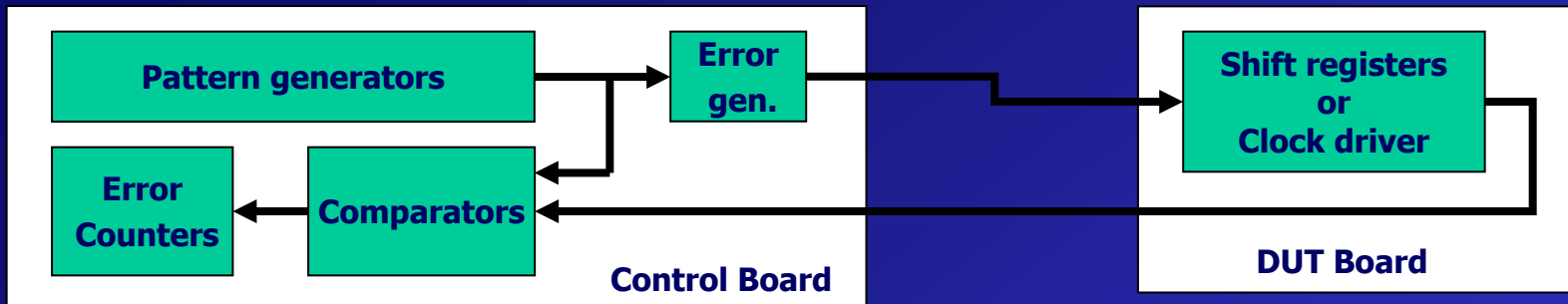
	Total dose (Rad) (10 years)	1 MeV Neutron eq. (10 years)	Hadrons > 20 MeV (10 years)
M1 (IB/ODE)	7 – 7.9 x 10 ³	9 – 9.8 x 10 ¹¹	4.3 – 5 x 10 ¹⁰
M2 (IB/ODE)	1.7 – 2.2 x 10 ³	3.2 – 3.4 x 10 ¹¹	1.8 – 1.9 x 10 ¹⁰
M3 (IB/ODE)	580 - 680	1.8 x 10 ¹¹	7.3 – 7.9 x 10 ⁹
M4 (IB/ODE)	180 - 390	1.2 – 1.9 x 10 ¹¹	2.6 – 5.3 x 10 ⁹
M5 (IB/ODE)	130 - 320	2.5 – 2.6 x 10 ¹¹	4.3 – 4.5 x 10 ⁹
Bunker	400 - 700	5.6 – 9.6 x 10 ¹¹	1.5 – 2.9 x 10 ¹⁰

- Safety factor 2 due to simulation included
- M1 now in a safer environment
- Total Integrated Dose (TID) of few Krad
 - Not a main concern in modern devices
- More stringent requirements for SEE and NIEL effect
 - Functional or destructive failures
 - SEL immune
 - Long term performances degradation

Component	Tested by	Tech.
GOL	CERN MIC	Rad-Tol
TTCrx	CERN MIC	Rad-Tol
QPLL	CERN MIC	Rad-Tol
SYNC	INFN-Cagliari	Rad-Tol
ELMB board	ATLAS	COTS
VCsel ULM850-05	LHCb ST	COTS
Agilent transmitter HFBR772	LHCb Muon Marseille	COTS
True-light PIN-preamp TRR-1B43-000	CERN	COTS
JTAG controller SN74LVT8980	ATLAS	COTS
Flash RAM AT45DB041B	LHCb Muon INFN-Roma1	COTS
Actel ProAsicPlus FPGA APA300	LHCb Muon INFN - LNF	COTS
Clock Driver MC100LVEP111	LHCb Muon INFN - LNF	COTS
Clock Driver MC100LVEP14	LHCb Muon INFN - LNF	COTS



- DUT are mounted on three types of piggy board (up to 4 devices per board)
- Piggy boards are hosted on a single motherboard in the beam area
 - Control board and LVDS drivers/receivers are 2 meters away from the beam spot
- The control board allows:
 - To power DUT (3.3 V, 2.5V, 1.5V) via on board regulators
 - To monitor DUT I/O and core currents via 11 bit ADC (1 mA resolution)
 - To send known patterns to DUT and to receive DUT output signals
 - To verify sent and received patterns, counting the errors
 - To write and read DUT RAM blocks
 - To communicate via RS232 with a computer for settings, monitor and data readout



- FPGA Logic Test
 - 3 “regular” shift registers + 1 “TMR” shift register implemented in the FPGA
 - 1024 bit shift registers in APA FPGA (75% of flip-flops)
 - 3 different patterns used
 - “0”, “1” pattern to verify different sensitivity
 - “01” pattern to verify clock upset and control logic upset
 - Shift register clocked at 1 MHz
 - Error forced every $2^{24}-1$ bits for self-testing
 - I/O and Core current monitored
- FPGA RAM test
 - Static test comparing pre-irradiation and post-irradiation memory bit maps
 - APA SRAM block configured as 1x4096 bit
- Clock Driver Test
 - Clock at 1 MHz
 - 1 output channel per device observed

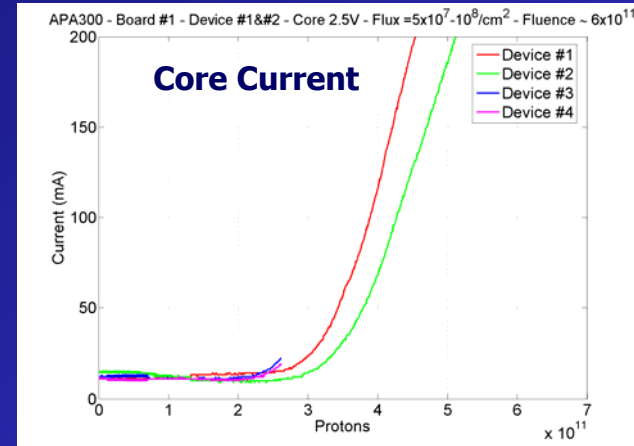
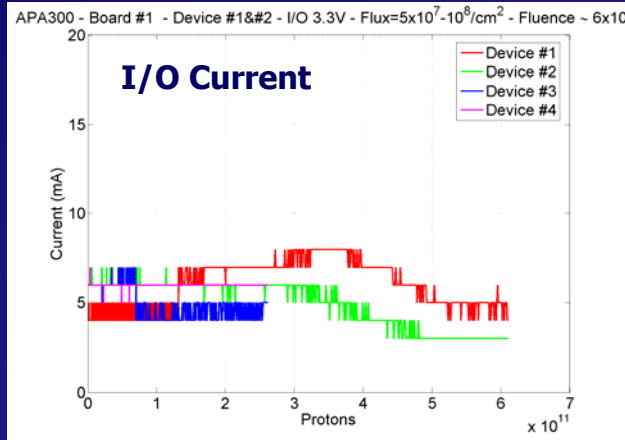
- Proton beam at Louvain la Neuve Cyclotron
- Energy: ~ 70 MeV
- Beam size: 9 cm \varnothing
- 4 devices irradiated
- Nominal flux used
 - 5×10^7 protons $\text{cm}^{-2} \text{s}^{-1}$ up to 10^{11} protons cm^{-2}
 - 5×10^8 protons $\text{cm}^{-2} \text{s}^{-1}$ up to 6×10^{11} protons cm^{-2}
- Fluence of 6×10^{11} protons cm^{-2} correspond to:
 - $\sim 6 \times 10^{11}$ “energetic” hadrons (~ 200 years of LHCb muon life)
 - ~ 68.5 krad of TID (~ 300 years of LHCb muon life)
 - $\sim 9 \times 10^{11}$ neutrons cm^{-2} for NIEL (~ 10 years of LHCb muon life)



	Device A			Device B			Device C			Device D		
Fluence p/cm ²	"0" pattern	"1" pattern	"01" pattern	"0" pattern	"1" pattern	"01" pattern	"0" pattern	"1" pattern	"01" pattern	"0" pattern	"1" pattern	"01" pattern
10 ¹¹	0	1	2	0	5	2	1	4	3	0	5	1
2 x 10 ¹¹	0	5	1	2	0	3	0	2	7	2	3	4
3 x 10 ¹¹	2	3	4	5	2	2	2	2	1	1	4	2
4 x 10 ¹¹	-	-	-	-	-	-	2	2	3	0	4	4
5 x 10 ¹¹	-	-	-	-	-	-	2	4	4	0	0	5
6 x 10 ¹¹	-	-	-	-	-	-	1	1	1	0	0	1
TOT	2	9	7	7	7	7	8	15	19	3	16	17
σ_{bit} (10 ⁻¹⁴)	0.65	2.9	2.3	2.3	2.3	2.3	1.3	2.4	3.1	0.5	2.6	2.8

- Low SEU cross section per bit $\rightarrow \sim 10^{-14}$
 - "1" pattern slightly more sensitive (?)
- No SEU in TMR shift registers
- No clock or control logic upset observed
- No SEL detected

- Core current start to increase at a fluence of 2.5×10^{11} protons/cm² (~ 35 krad)
 - Devices continue to work



- SEU RAM cross section per bit $\sim 10^{-13}$

	Device A	Device B	Device C	Device D
Fluence p/cm ²	Ram Upset	Ram Upset	Ram Upset	Ram Upset
10^{11}	27	40	38	42
2×10^{11}	53	30	-	
6×10^{11}	-	-	153	199
TOT	80	70	191	241
σ_{bit} (10^{-14})	9.7	8.5	7.8	9.8

- MC100LVEP111
 - No SEU observed up to a fluence of 6×10^{11} protons/cm²
 - Cross section per bit $< 8.3 \times 10^{-13}$ cm² protons⁻¹ bit⁻¹
 - No SEL detected
 - No current change @ 6×10^{11} protons/cm²
- MC100LVEP14
 - 7 SEU observed with a fluence of 6×10^{11} protons/cm²
 - Cross section per bit = 5.8×10^{-12} cm² protons⁻¹ bit⁻¹
 - No SEL detected
 - No current change @ 6×10^{11} protons/cm²

ODE components

Component	Tested by		TID	SEE	reference
GOL	CERN MIC	Rad-Tol			
TTCrx	CERN MIC	Rad-Tol			Proceedings of the 6th Workshop on Electronics for LHC Experiments
QPLL	CERN MIC	Rad-Tol			http://www.cern.ch/proj-qpll/images/qpll2IrradData.pdf
SYNC	INFN - Cagliari	Rad-Tol			Note in preparation
ELMB board	ATLAS	COTS	14 krad	6×10^{12} n/cm² (1 MeV equivalent) 1×10^{11} p/cm² (60 MeV)	ATLAS Internal Working Note DCS- IWN20, DCS- IWN21, DCS- IWN23
VCsel ULM850-05	LHCb ST	COTS	300 krad	3.6×10^{12} n/cm² (1 MeV equivalent)	LHCb note 2004-037
Agilent transmitter HFBR772	LHCb Muon Marseille	COTS	15 krad	2.5×10^{11} p/cm² (250 MeV)	LHCb note 2004-013
True-light PIN-preamp TRR-1B43-000	CERN	COTS	1 Mrad	7×10^{13} n/cm² (1 MeV equivalent) 1.2×10^{11} p/cm² (60 MeV)	Proceedings of the 9th Workshop on Electronics for LHC Experiments,
JTAG controller SN74LVT8980	ATLAS	COTS	30 krad	2.3×10^{11} p/cm² (70 MeV)	http://atlas.web.cern.ch/Atlas/GROUPS/FRONTEND/radhard_MUON_TGC.htm
Flash RAM AT45DB041B	LHCb Muon INFN - Roma1	COTS	20 krad	2×10^{11} p/cm² (60 MeV)	Note in preparation
Actel ProAsicPlus FPGA APA300	LHCb Muon INFN - LNF	COTS	68 krad	9×10^{11} n/cm² (1 MeV equivalent) 6×10^{11} p/cm² (70 MeV)	Note in preparation
Clock Driver MC100LVEP111	LHCb Muon INFN - LNF	COTS	68 krad	9×10^{11} n/cm² (1 MeV equivalent) 6×10^{11} p/cm² (70 MeV)	Note in preparation
Clock Driver MC100LVEP14	LHCb Muon INFN - LNF	COTS	68 krad	9×10^{11} n/cm² (1 MeV equivalent) 6×10^{11} p/cm² (70 MeV)	Note in preparation

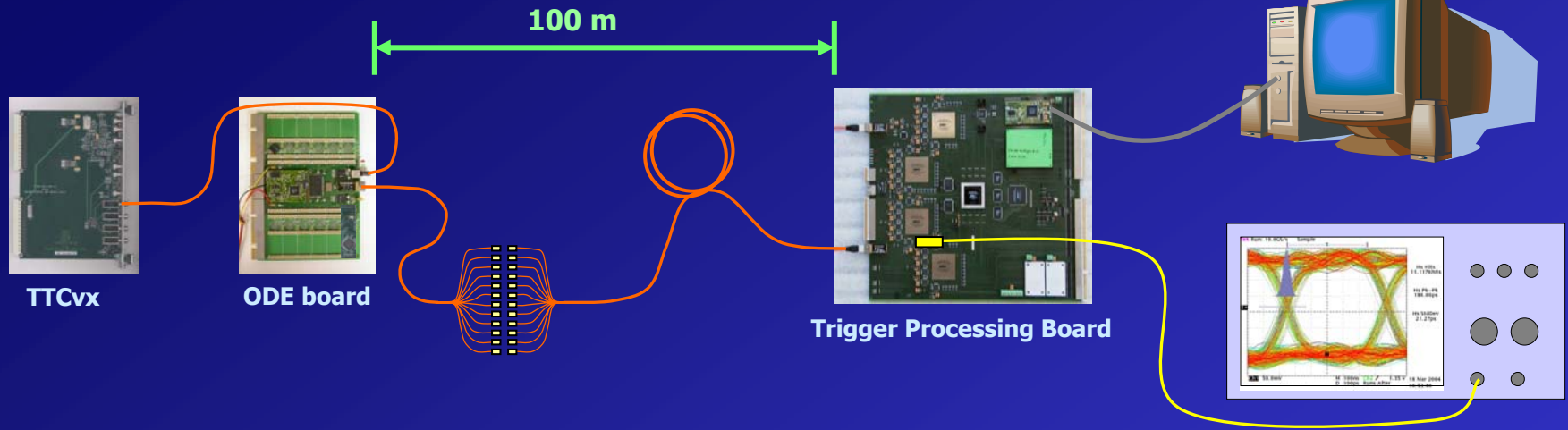
- NO SEL detected
- No performances degradation observed for NIEL

- FPGA Hard SEE
 - Possible ODE permanent damage
 - Main worry in the first flash-based FPGA
 - From Actel tests no latch-up has been observed for LET higher than 100 MeV cm²/mg for APA FPGA
 - This threshold should guarantee our system free from SEL
- FPGA SOFT SEE
 - Possible loss of ODE functionalities
 - 148 FPGA in the muon L0 electronics
 - Each FPGA uses
 - ~ 2000 flip-flops (without TMR)
 - 512 RAM bit
 - In the worst case
 - $3 \times 10^{-14} \times 5 \times 10^{10} \times 2000 \times 148 = 444$ flip-flop upsets in 10 years
 - $10^{-13} \times 3 \times 10^{10} \times 512 \times 148 = 227$ RAM bit upsets in 10 years
 - The foreseen TMR technique and EDAC coding allow to improve system reliability
- Clock Upset
 - Possible ODE misalignment and GOL loss of lock
 - 6 MC100LVEP14 (4 channels) per ODE (148 board)
 - $5.8 \times 10^{-12} \times 5 \times 10^{10} \times 4 \times 6 \times 148 = 1030$ upsets in 10 years

- HFBR772 upset
 - “The cross-section for single event upsets is equal to $(4.5 \pm 0.1) \times 10^{-10} \text{cm}^2$ per single optical link. The corresponding inefficiency on the level-0 muon trigger is below 10^{-10} and therefore negligible.” [LHCb note 2004-013]
- GOL, TTCrx, QPLL and SYNC upset
 - Rad-Tol technology
 - Negligible effect
- ELMB upset
 - Loss of ECS communication
 - No functional problems on the ODE (!)
 - ELMB can be reset through
 - Internal watchdog system
 - A “reset board” seated in the crate and controllable by ECS
- JTag controller and Flash Ram upset
 - No functional problems on the ODE

TEST ...

ODE – L0 muon trigger test



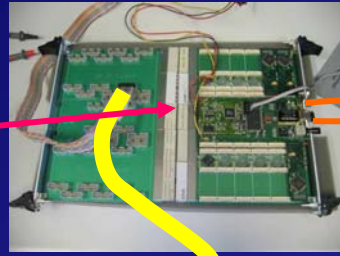
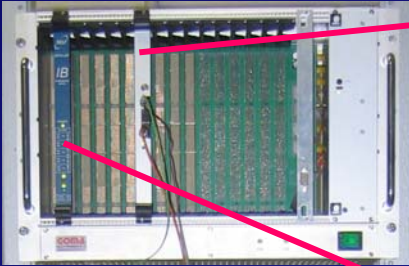
- ODE (first prototype) and the muon trigger processing board with 100 m ribbon fiber
- System clock generated by a TTCvx
 - Telecom frequency (77.76 MHz)
 - Maxim PLL+VCXO for clock de-jitter
- Data generated by the SYNC chips using their test features
 - Transmission of consecutive IDLE words
 - Transmission of fixed patterns wrote on SYNC through I²C interface
 - Transmission of a Pseudo-random pattern generated on SYNC
- Received Data monitored on a PC and oscilloscope TDS694C
 - Check data integrity and synchronization
 - Well open eye diagram
 - Max peak-to-peak jitter 186 ps ($\sigma \sim 21$ ps)

- 1 Muon Chamber
 - 12 CARDIAC (96 channels)
- 1 IB (+ TB) on custom crate
- 1 ODE (+ TB) on custom crate
- 1 VME crate with
 - 1 SB
 - 1 TTCvx
 - 1 TTCvi
 - Clock generator (custom) board
 - Optical Receiver board (custom)
 - 1 interface VME-PCI
- Control PC with
 - PVSS
 - KVASER board (PCI-CAN interface)
 - ODE control software
- Pattern generator and Logic Analyzer

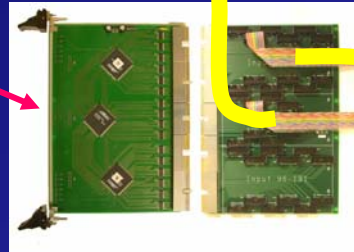


Chain setup

Custom crate

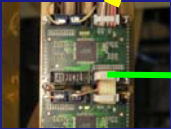


ODE + TB

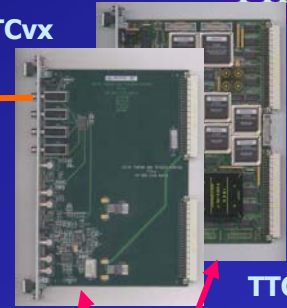


IB + TB

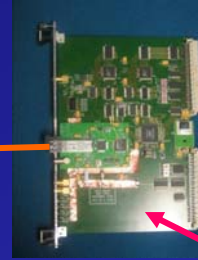
CARDIAC



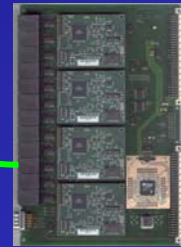
TTCvx



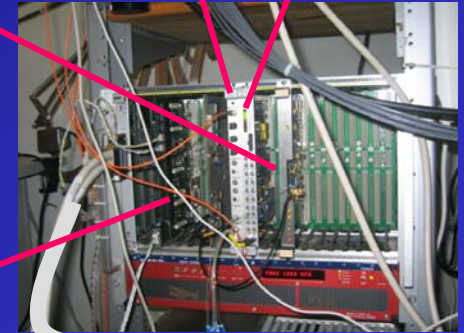
TTCvi



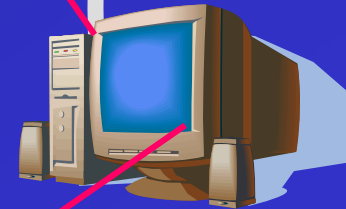
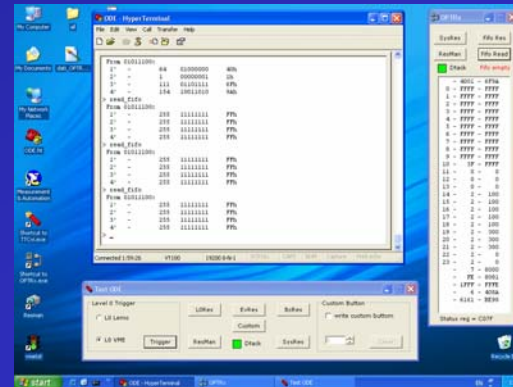
Optical receiver



SB

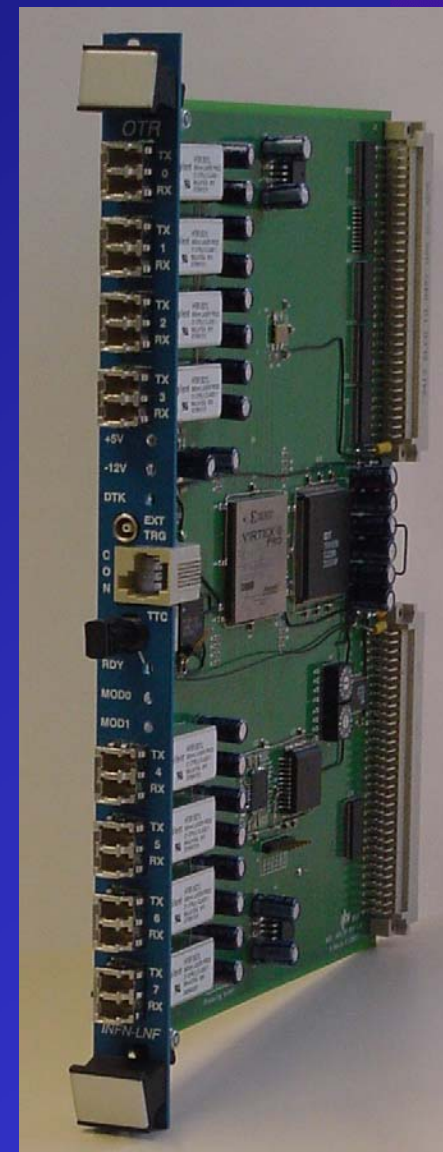


VME crate



- TTC interface
 - TTC command (L0yes, L0_res, BC_res, Ev_res) sent using TTCvi+TTCvx
 - Command correctly received, decoded and distributed on the ODE
- Front-end, trigger and DAQ interfaces
 - Using the pulse functionality on SB and DIALOG,
 - generate specific DIALOG inputs and find them in the right place at the end of the chain
 - generate specific DIALOG inputs put in specific logical combination among them and find the right logical channel (only) in the right place at the end of the chain. 2 kinds of combinations were possible:
 - 2 logical channels starting from 4 physical channels (2xOR2)
 - 1 logical channel starting from 4 physical channels (1xOR4)
 - Data checked directly at the end of the chain following the 2 possible data links (Trigger and DAQ)
 - Both checks performed by reading data on a FIFO in the optical receiver board
 - Verifying correctness of data frame and synchronization
- ECS interface
 - ODE configuration
 - SYNC histogram read-back

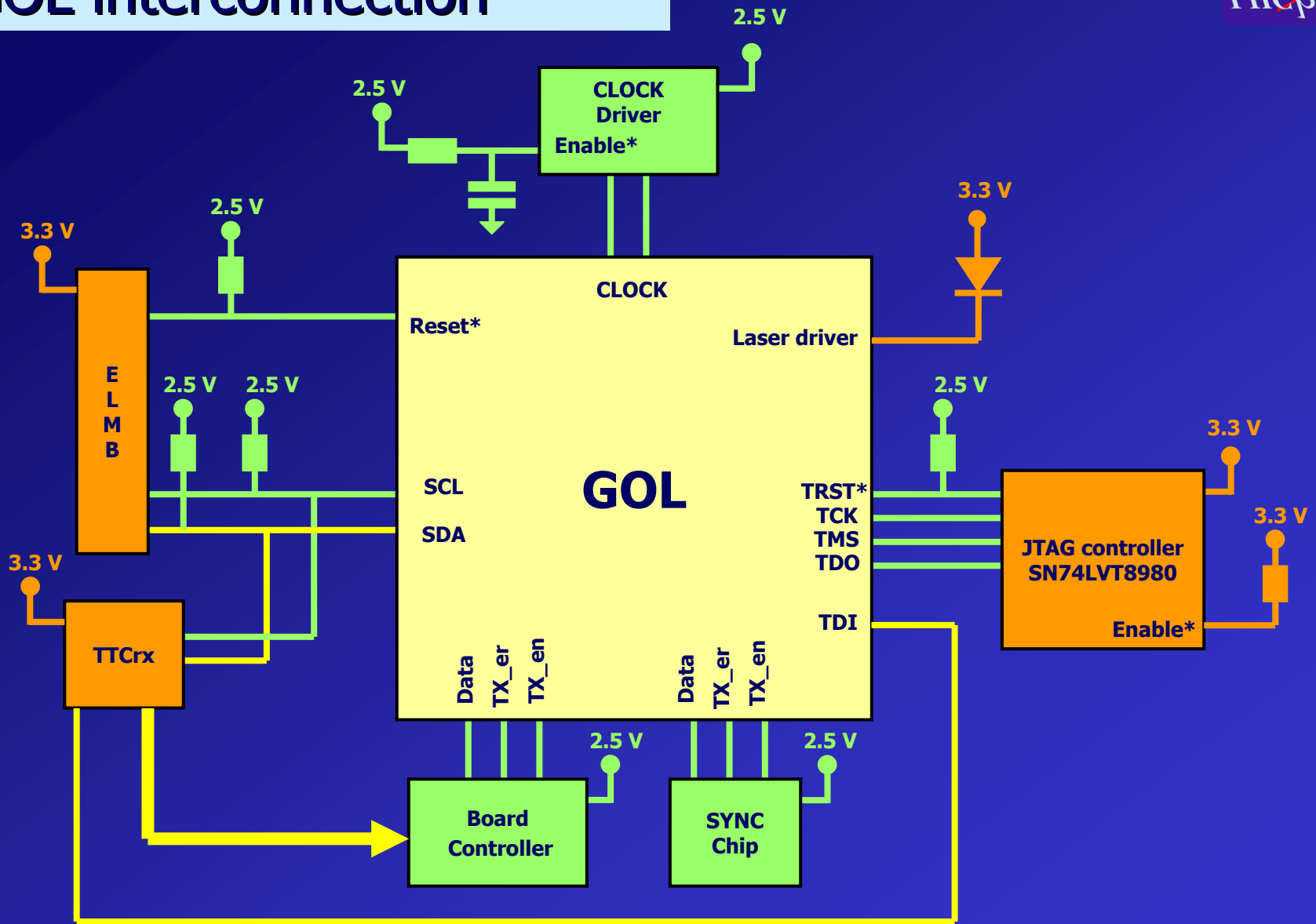
- Quality assurance on board assembly (factory)
- TTC interface test
 - TTCvi + TTCvx
 - Synchronization and command decoding test
- Front-end input test
 - SYNC chip already tested
 - Patter generator or random pulses
 - Histogram from SYNC
- Trigger and DAQ link test
 - BERT up to 10^{-12} using ODE test features
 - Custom 6U VME board
 - 8 full duplex optical channel
 - VirtexIIPRO
 - 8 full duplex serial transceivers @3.125 Gbit/s
 - IBM 400MHz PowerPC™
 - 400 MHz clock rate
 - TTCrx + QPLL for system synchronization
 - 528 Kbytes fast dual port RAM
- ECS interface test
 - Board initialization and test via CANbus interface



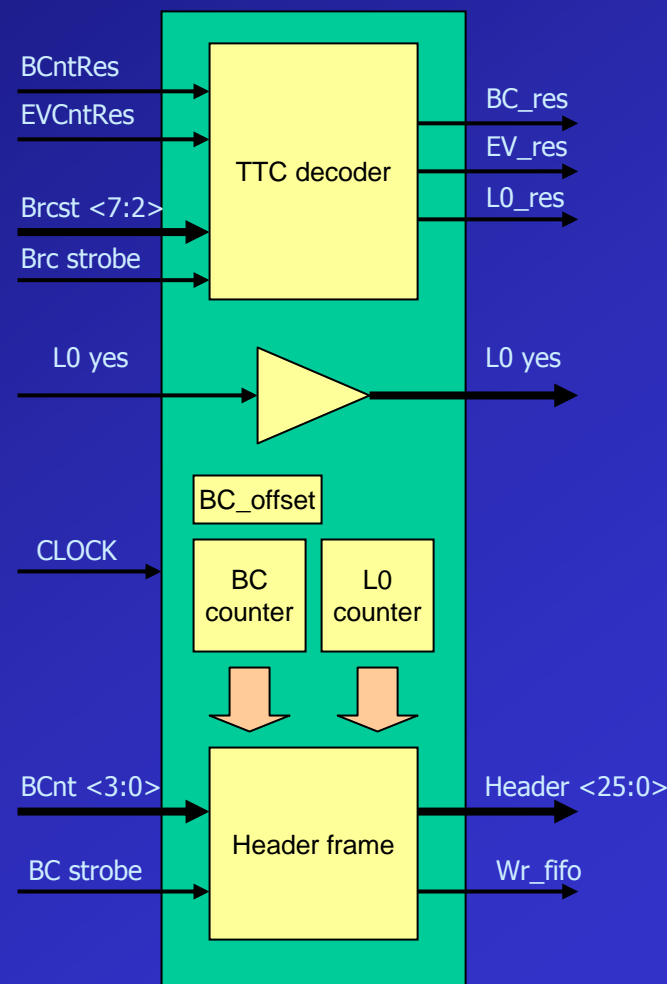
- ODE board fully characterized
 - Architecture well defined
 - Low jitter clock network
 - 50 ps peak-to-peak
 - Low BER optical links for trigger and DAQ
 - 10^{-16} estimated BER
 - 10^{-12} measured BER
 - Good radiation hardness assurance
- ODE board fulfils the experiment requirements
 - L0 requirements
 - Buffering, consecutive triggers, alignment check, test features, ...
 - Trigger and DAQ systems requirements
 - Formatting, transmission quality, ...
- Ready for the pre-production
 - Production test-stand defined

Spare slides

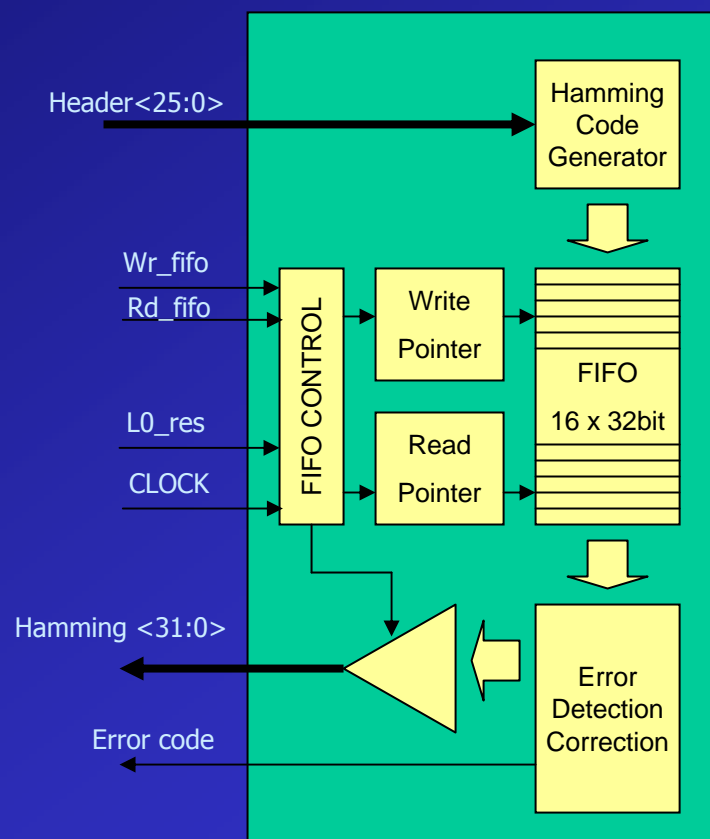
GOL interconnection



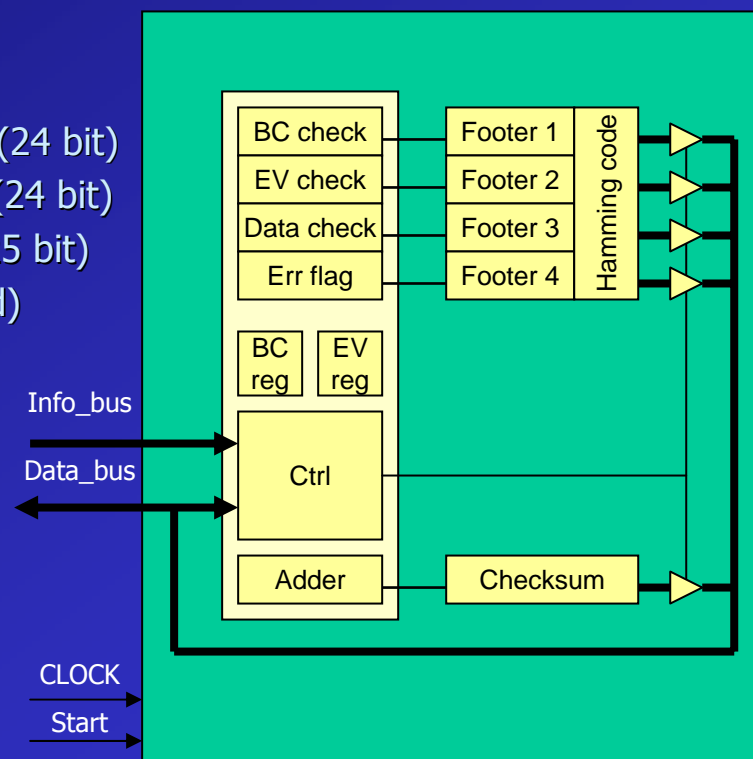
- Receive signals from TTCrx
 - Decode broadcast command
 - Bunch-ID reset (BC_res)
 - L0 Event ID reset (EV_res)
 - L0 reset (L0_res)
 - Distribute resets and L0 trigger signals
- Internal 12 bit Bunch-ID counter (BC_Id)
 - Synchronous reset with BC_res
 - Predefined BC_offset loaded at BC_res
- Internal 12 bit L0 Event-ID counter (L0_Id)
 - Synchronous reset with EV_res or L0_res
 - First L0 trigger after a counter reset \Rightarrow L0_Id=0
- For each L0 trigger
 - Check internal BC_Id vs TTCrx BCnt
 - Generate header word (25 bit)
 - 1 check bit + 12 bit L0_Id + 12 bit BC_Id
 - Generate header FIFO write



- Allow consecutive L0 trigger
 - 16 words deep
 - 32/64 in final version (?)
- Data protected by Hamming code
 - Single error detection and correction
 - Double error detection
 - 6 extra code bit
- Data discharged at FIFO full
- FIFO reset with L0_res

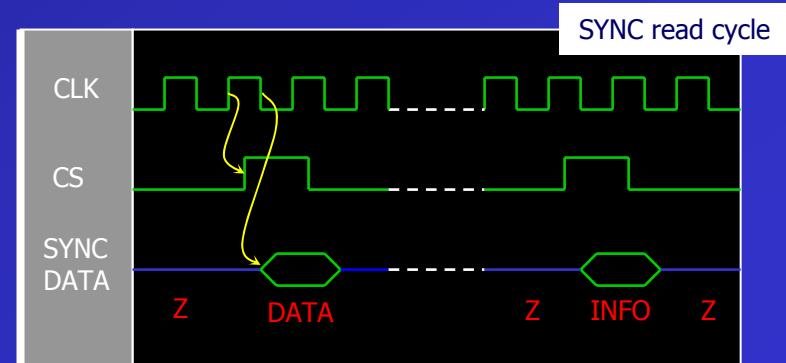
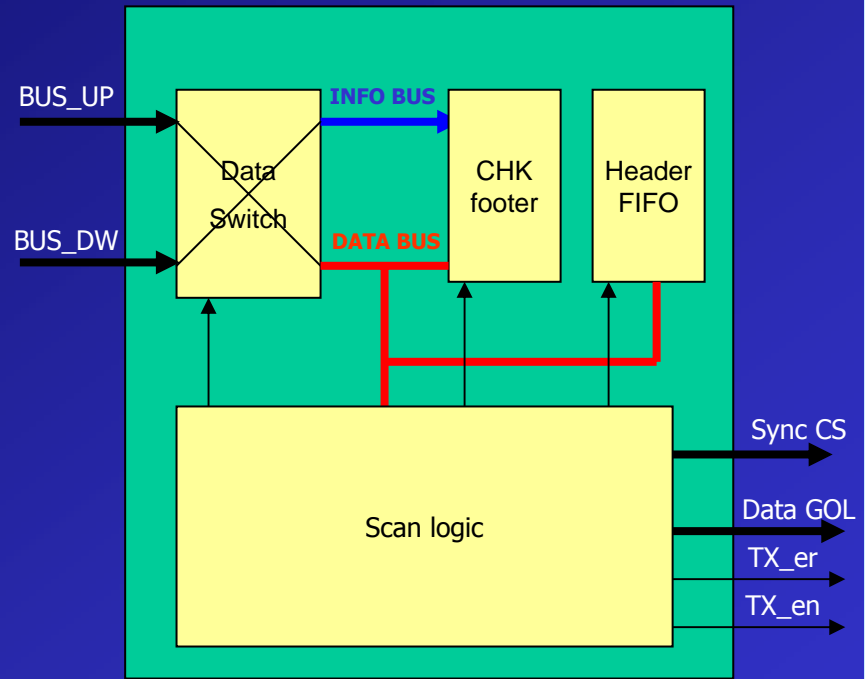


- Receive INFO word
 - 4 bit SYNC BX_Id
 - 4 bit SYNC EV_Id
 - 2 bit SYNC data error (double error detection)
- Generate 4 footer check words
 - BX_Id alignment of each SYNC vs internal BC_Id (24 bit)
 - EV_Id alignment of each SYNC vs internal LO_Id (24 bit)
 - Data error of each SYNC + internal FIFO error (25 bit)
 - Board address + Error flags (not yet implemented)
- Footer protected by Hamming code
- Calculate frame checksum
 - 32 bit adder without carry
 - Header
 - 24 data words
 - 4 footer check words

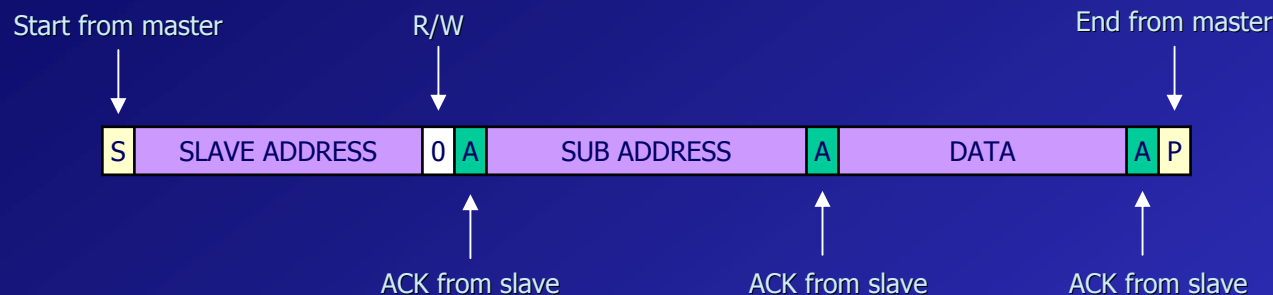


Scan logic

- Scan start if header FIFO is not empty
- Drive GOL transmission
- Read header FIFO
 - Store BC_Id and L0_Id in internal registers
 - Send hamming header to GOL
- Read SYNC chip in parallel mode
 - Drive dataswitch to redirect BUS_UP and BUS_DW on internal buses
 - For the first 12 clock cycles
 - Receive data word on BUS_UP
 - Receive info word on BUS_DW
 - For the second 12 clock cycles
 - Receive data word on BUS_DW
 - Receive info word on BUS_UP
 - Send data words to GOL with 1-level pipeline
- Read and send footer check words and checksum to GOL



- I²C interface implemented on L0 controller
 - Write cycle



- Read cycle

